

EMBEDDED WRITE-BACK ENHANCED IntelDX4™ PROCESSOR

- Up to 100 MHz Operation
- Integrated Floating-Point Unit
- Speed-Multiplying Technology
- 32-Bit RISC Technology Core
- 16-Kbyte Write-Back Cache
- 3.3 V Core Operation with 5 V Tolerant I/O Buffers
- Burst Bus Cycles
- Dynamic Bus Sizing for 8- and 16-bit Data Bus Devices
- SL Technology
- Data Bus Parity Generation and Checking
- Boundary Scan (JTAG)
- 3.3-Volt Processor, 75 MHz, 25 MHz CLK
 - 208-Lead Shrink Quad Flat Pack (SQFP)
- 3.3-Volt Processor, 100 MHz, 33 MHz CLK
 - 208-Lead Shrink Quad Flat Pack (SQFP)
 - 168-Pin Pin Grid Array (PGA)
- Binary Compatible with Large Software Base

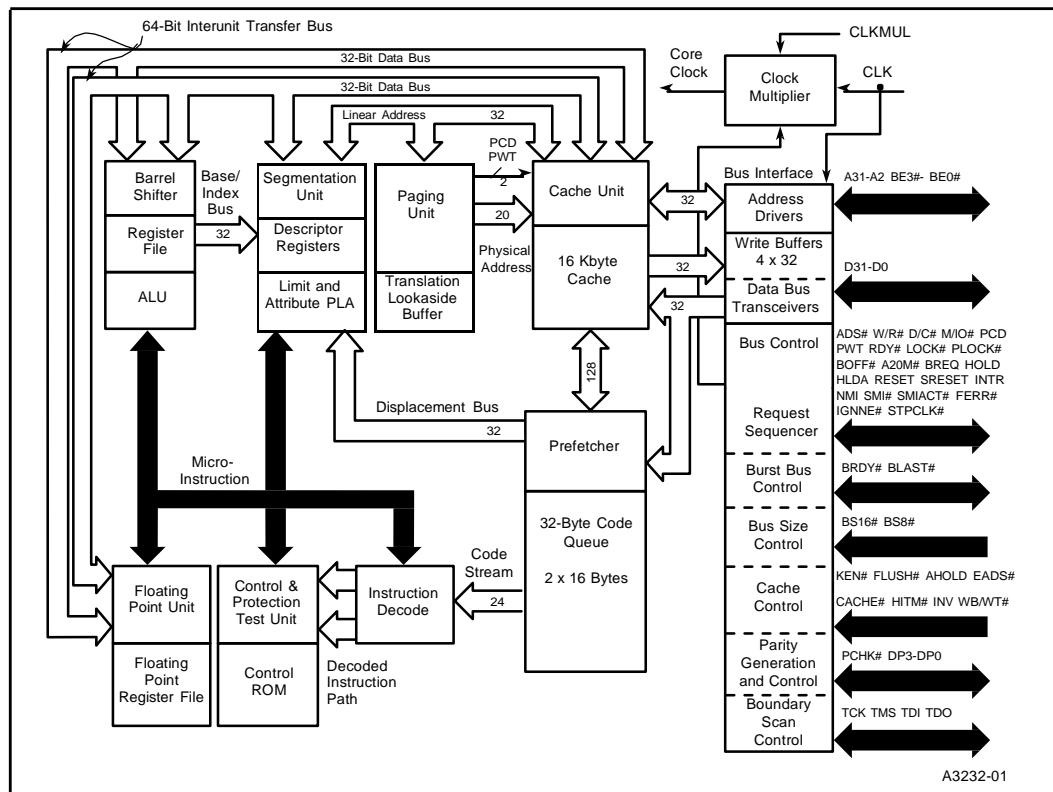


Figure 1. Embedded Write-Back Enhanced IntelDX4™ Processor Block Diagram

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EMBEDDED WRITE-BACK ENHANCED IntelDX4™ PROCESSOR

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1.0 INTRODUCTION

The embedded Write-Back Enhanced IntelDX4™ processor provides high performance to 32-bit, embedded applications. Designed for applications that need a floating-point unit, the processor is ideal for embedded designs running DOS*, Microsoft Windows*, OS/2*, or UNIX* applications written for the Intel architecture. Projects can be completed quickly using the wide range of software tools, utilities, assemblers and compilers that are available for desktop computer systems. Also, developers can find advantages in using existing chipsets and peripheral components in their embedded designs.

The Embedded Write-Back Enhanced IntelDX4 processor is binary compatible with the Intel386™ and earlier Intel processors. Compared with the Intel386 processor, it provides faster execution of many commonly-used instructions. It also provides the benefits of an integrated, 16-Kbyte, write-back cache for code and data. Its data bus can operate in burst mode which provides up to 106-Mbyte-per-second transfers for cache-line fills and instruction prefetches.

Intel's SL technology is incorporated in the Embedded Write-Back Enhanced IntelDX4 processor. Utilizing Intel's System Management Mode (SMM) enables designers to develop energy-efficient systems.

Two component packages are available:

- 168-pin Pin Grid Array (PGA)
- 208-lead Shrink Quad Flat Pack (SQFP)

The processor operates at either two or three times the external bus frequency. At two times the external bus frequency the processor operates up to 66 MHz, (33-MHz CLK). At three times the external bus frequency the processor operates up to 100 MHz (33-MHz CLK).

1.1 Features

The Embedded Write-Back Enhanced IntelDX4 processor offers these features:

- **32-bit RISC-Technology Core** — The Embedded Write-Back Enhanced IntelDX4 processor performs a complete set of arithmetic and logical operations on 8-, 16-, and 32-bit data types using a full-width ALU and eight general purpose registers.
- **Single Cycle Execution** — Many instructions execute in a single clock cycle.
- **Instruction Pipelining** — Overlapped instruction fetching, decoding, address translation and execution.
- **On-Chip Floating-Point Unit** — Intel486™ processors support the 32-, 64-, and 80-bit formats specified in IEEE standard 754. The unit is binary compatible with the 8087, Intel287™, Intel387™ coprocessors, and Intel OverDrive® processor.
- **On-Chip Cache with Cache Consistency Support** — A 16-Kbyte internal cache is used for both data and instructions. It is configurable to be write-back or write-through on a line-by-line basis. The internal cache implements a modified MESI protocol, which is applicable to uniprocessor systems. Cache hits provide zero wait-state access times for data within the cache. Bus activity is tracked to detect alterations in the memory represented by the internal cache. The internal cache can be invalidated or flushed so that an external cache controller can maintain cache consistency.
- **External Cache Control** — Write-back and flush controls for an external cache are provided so the processor can maintain cache consistency.
- **On-Chip Memory Management Unit** — Address management and memory space protection mechanisms maintain the integrity of memory in a multitasking and virtual memory environment. Both memory segmentation and paging are supported.
- **Burst Cycles** — Burst transfers allow a new double-word to be read from memory on each bus clock cycle. This capability is especially useful for instruction prefetch and for filling the internal cache. Data written from the processor to memory can also be burst transfers.
- **Write Buffers** — The processor contains four write buffers to enhance the performance of consecutive writes to memory. The processor can continue internal operations after a write to these buffers, without waiting for the write to be completed on the external bus.

- **Bus Backoff** — When another bus master needs control of the bus during a processor initiated bus cycle, the Embedded Write-Back Enhanced IntelDX4 processor floats its bus signals, then restarts the cycle when the bus becomes available again.
- **Instruction Restart** — Programs can continue execution following an exception generated by an unsuccessful attempt to access memory. This feature is important for supporting demand-paged virtual memory applications.
- **Dynamic Bus Sizing** — External controllers can dynamically alter the effective width of the data bus. Bus widths of 8, 16, or 32 bits can be used.
- **Boundary Scan (JTAG)** — Boundary Scan provides in-circuit testing of components on printed circuit boards. The Intel Boundary Scan implementation conforms with the IEEE Standard Test Access Port and Boundary Scan Architecture.
- **Enhanced Bus Mode** — The definitions of some signals have been changed to support write-back cache mode.
- **Stop Clock** — The Embedded Write-Back Enhanced IntelDX4 processor has a stop clock control mechanism that provides two low-power states: a Stop Grant state (20–50 mA typical, depending on input clock frequency) and a Stop Clock state (~600 A typical, with input clock frequency of 0 MHz).
- **Auto HALT Power Down** — After the execution of a HALT instruction, the Embedded Write-Back Enhanced IntelDX4 processor issues a normal Halt bus cycle and the clock input to the processor core is automatically stopped, causing the processor to enter the Auto HALT Power Down state (20–50 mA typical, depending on input clock frequency).
- **Auto Idle Power Down** — This function allows the processor to reduce the core frequency to the bus frequency when both the core and bus are idle. Auto Idle Power Down is software transparent and does not affect processor performance. Auto Idle Power Down provides an average power savings of 10% and is only applicable to clock multiplied processors.

Intel's SL technology provides these features:

- **Intel System Management Mode (SMM)** — A unique Intel architecture operating mode provides a dedicated special purpose interrupt and address space that can be used to implement intelligent power management and other enhanced functions in a manner that is completely transparent to the operating system and applications software.
- **I/O Restart** — An I/O instruction interrupted by a System Management Interrupt (SMI#) can automatically be restarted following the execution of the RSM instruction.

1.2 Family Members

Table 1 shows the Embedded Write-Back Enhanced IntelDX4 processors and briefly describes their characteristics.

Table 1. The Embedded Write-Back Enhanced IntelDX4™ Processor Family

| Product | Supply Voltage V_{cc} | Maximum Processor Frequency | Maximum External Bus Frequency | Package |
|-----------------|----------------------------|-----------------------------------|--------------------------------------|---------------|
| FC80486DX4WB75 | 3.3 V | 75 MHz | 25 MHz | 208-Lead SQFP |
| FC80486DX4WB100 | 3.3 V | 100 MHz | 33 MHz | 208-Lead SQFP |
| A80486DX4WB100 | 3.3 V | 100 MHz | 33 MHz | 168-Pin PGA |

2.0 HOW TO USE THIS DOCUMENT

For a complete set of documentation related to the Embedded Write-Back Enhanced IntelDX4 processor, use this document in conjunction with the following reference documents:

- Embedded Intel486™ Processor Family Developer's Manual — Order No. 273021
- Embedded Intel486™ Processor Hardware Reference Manual — Order No. 273025
- Intel486 Microprocessor Family Programmer's Reference Manual — Order No. 240486
- Intel Application Note AP-485 — Intel Processor Identification with the CPUID Instruction — Order No. 241618

The information in the reference documents for the IntelDX4 processor applies to the Embedded Write-Back Enhanced IntelDX4 processor. Some of the IntelDX4 processor information is duplicated in this document to minimize the dependence on the reference documents.

3.0 PIN DESCRIPTIONS

3.1 Pin Assignments

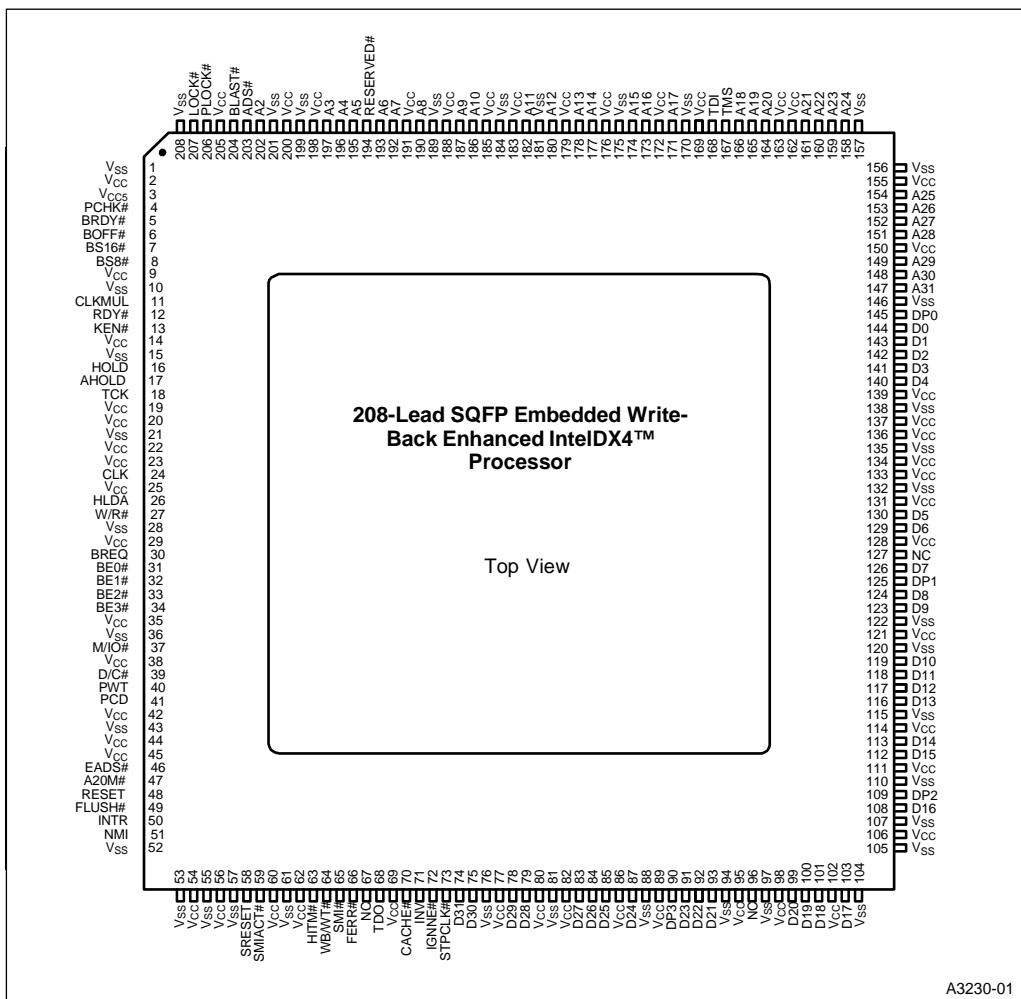
The following figures and tables show the pin assignments of each package type for the Embedded Write-Back Enhanced IntelDX4 processor. Tables are provided showing the pin differences between the Embedded Write-Back Enhanced IntelDX4 processor and other embedded Intel486 processor products.

208-Lead SQFP - Quad Flat Pack

- Figure 2, Package Diagram for 208-Lead SQFP Embedded Write-Back Enhanced IntelDX4™ Processor (pg. 4)
- Table 2, Pinout Differences for 208-Lead SQFP Package (pg. 5)
- Table 3, Pin Assignment for 208-Lead SQFP Package (pg. 6)
- Table 4, Pin Cross Reference for 208-Lead SQFP Package (pg. 8)

168-Pin PGA - Pin Grid Array

- Figure 3, Package Diagram for 168-Pin PGA Embedded Write-Back Enhanced IntelDX4™ Processor (pg. 10)
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- Table 6, Pin Assignment for 168-Pin PGA Package (pg. 12)
- Table 7, Pin Cross Reference for 168-Pin PGA Package (pg. 14)



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Figure 2. Package Diagram for 208-Lead SQFP Embedded Write-Back Enhanced IntelDX4™ Processor

Table 2. Pinout Differences for 208-Lead SQFP Package

| Pin # | Embedded Intel486™ SX Processor | Embedded IntelDX2™ Processor | Embedded Write-Back Enhanced IntelDX4™ Processor |
|-------|---------------------------------------|------------------------------------|--|
| 3 | V_{CC}^1 | V_{CC} | V_{CC5} |
| 11 | INC ² | INC | CLKMUL |
| 63 | INC | INC | HITM# |
| 64 | INC | INC | WB/WT# |
| 66 | INC | FERR# | FERR# |
| 70 | INC | INC | CACHE# |
| 71 | INC | INC | INV |
| 72 | INC | IGNNE# | IGNNE# |

NOTES:

1. This pin location is for the V_{CC5} pin on the embedded IntelDX4 processor. For compatibility with 3.3V processors that have 5V-tolerant input buffers (i.e., embedded IntelDX4 processors), this pin should be connected to a V_{CC} trace, not to the V_{CC} plane.
2. INC. Internal No Connect. These pins are not connected to any internal pad. However, signals are defined for the location of the INC pins in the embedded IntelDX4 processor. One system design can accommodate any one of these processors provided the purpose of each INC pin is understood before it is used.

Table 3. Pin Assignment for 208-Lead SQFP Package (Sheet 1 of 2)

| Pin# | Description | Pin# | Description | Pin# | Description | Pin# | Description |
|------|------------------|------|-----------------|------|-----------------|------|-----------------|
| 1 | V _{SS} | 53 | V _{SS} | 105 | V _{SS} | 157 | V _{SS} |
| 2 | V _{CC} | 54 | V _{CC} | 106 | V _{CC} | 158 | A24 |
| 3 | V _{CC5} | 55 | V _{SS} | 107 | V _{SS} | 159 | A23 |
| 4 | PCHK# | 56 | V _{CC} | 108 | D16 | 160 | A22 |
| 5 | BRDY# | 57 | V _{SS} | 109 | DP2 | 161 | A21 |
| 6 | BOFF# | 58 | SRESET | 110 | V _{SS} | 162 | V _{CC} |
| 7 | BS16# | 59 | SMIACT# | 111 | V _{CC} | 163 | V _{CC} |
| 8 | BS8# | 60 | V _{CC} | 112 | D15 | 164 | A20 |
| 9 | V _{CC} | 61 | V _{SS} | 113 | D14 | 165 | A19 |
| 10 | V _{SS} | 62 | V _{CC} | 114 | V _{CC} | 166 | A18 |
| 11 | CLKMUL | 63 | HITM# | 115 | V _{SS} | 167 | TMS |
| 12 | RDY# | 64 | WB/WT# | 116 | D13 | 168 | TDI |
| 13 | KEN# | 65 | SMI# | 117 | D12 | 169 | V _{CC} |
| 14 | V _{CC} | 66 | FERR# | 118 | D11 | 170 | V _{SS} |
| 15 | V _{SS} | 67 | NC ¹ | 119 | D10 | 171 | A17 |
| 16 | HOLD | 68 | TDO | 120 | V _{SS} | 172 | V _{CC} |
| 17 | AHOLD | 69 | V _{CC} | 121 | V _{CC} | 173 | A16 |
| 18 | TCK | 70 | CACHE# | 122 | V _{SS} | 174 | A15 |
| 19 | V _{CC} | 71 | INV | 123 | D9 | 175 | V _{SS} |
| 20 | V _{CC} | 72 | IGNNE# | 124 | D8 | 176 | V _{CC} |
| 21 | V _{SS} | 73 | STPCLK# | 125 | DP1 | 177 | A14 |
| 22 | V _{CC} | 74 | D31 | 126 | D7 | 178 | A13 |
| 23 | V _{CC} | 75 | D30 | 127 | NC ¹ | 179 | V _{CC} |
| 24 | CLK | 76 | V _{SS} | 128 | V _{CC} | 180 | A12 |
| 25 | V _{CC} | 77 | V _{CC} | 129 | D6 | 181 | V _{SS} |
| 26 | HLDA | 78 | D29 | 130 | D5 | 182 | A11 |
| 27 | W/R# | 79 | D28 | 131 | V _{CC} | 183 | V _{CC} |
| 28 | V _{SS} | 80 | V _{CC} | 132 | V _{SS} | 184 | V _{SS} |
| 29 | V _{CC} | 81 | V _{SS} | 133 | V _{CC} | 185 | V _{CC} |
| 30 | BREQ | 82 | V _{CC} | 134 | V _{CC} | 186 | A10 |
| 31 | BE0# | 83 | D27 | 135 | V _{SS} | 187 | A9 |
| 32 | BE1# | 84 | D26 | 136 | V _{CC} | 188 | V _{CC} |
| 33 | BE2# | 85 | D25 | 137 | V _{CC} | 189 | V _{SS} |
| 34 | BE3# | 86 | V _{CC} | 138 | V _{SS} | 190 | A8 |
| 35 | V _{CC} | 87 | D24 | 139 | V _{CC} | 191 | V _{CC} |

Table 3. Pin Assignment for 208-Lead SQFP Package (Sheet 2 of 2)

| Pin# | Description | Pin# | Description | Pin# | Description | Pin# | Description |
|------|-----------------|------|-----------------|------|-----------------|------|-----------------|
| 36 | V _{SS} | 88 | V _{SS} | 140 | D4 | 192 | A7 |
| 37 | M/I/O# | 89 | V _{CC} | 141 | D3 | 193 | A6 |
| 38 | V _{CC} | 90 | DP3 | 142 | D2 | 194 | RESERVED# |
| 39 | D/C# | 91 | D23 | 143 | D1 | 195 | A5 |
| 40 | PWT | 92 | D22 | 144 | D0 | 196 | A4 |
| 41 | PCD | 93 | D21 | 145 | DP0 | 197 | A3 |
| 42 | V _{CC} | 94 | V _{SS} | 146 | V _{SS} | 198 | V _{CC} |
| 43 | V _{SS} | 95 | V _{CC} | 147 | A31 | 199 | V _{SS} |
| 44 | V _{CC} | 96 | NC ¹ | 148 | A30 | 200 | V _{CC} |
| 45 | V _{CC} | 97 | V _{SS} | 149 | A29 | 201 | V _{SS} |
| 46 | EADS# | 98 | V _{CC} | 150 | V _{CC} | 202 | A2 |
| 47 | A20M# | 99 | D20 | 151 | A28 | 203 | ADS# |
| 48 | RESET | 100 | D19 | 152 | A27 | 204 | BLAST# |
| 49 | FLUSH# | 101 | D18 | 153 | A26 | 205 | V _{CC} |
| 50 | INTR | 102 | V _{CC} | 154 | A25 | 206 | PLOCK# |
| 51 | NMI | 103 | D17 | 155 | V _{CC} | 207 | LOCK# |
| 52 | V _{SS} | 104 | V _{SS} | 156 | V _{SS} | 208 | V _{SS} |

NOTE:

1. NC. Do Not Connect. These pins should always remain unconnected. Connection of NC pins to V_{CC}, or V_{SS} or to any other signal can result in component malfunction or incompatibility with future steppings of the Intel486 processors.

Table 4. Pin Cross Reference for 208-Lead SQFP Package (Sheet 1 of 2)

| Address | Pin # | Data | Pin # | Control | Pin # | NC | V _{CC5} | V _{CC} | V _{SS} |
|---------|-------|------|-------|---------|-------|-----|------------------|-----------------|-----------------|
| A2 | 202 | D0 | 144 | A20M# | 47 | 67 | 3 | 2 | 1 |
| A3 | 197 | D1 | 143 | ADS# | 203 | 96 | | 9 | 10 |
| A4 | 196 | D2 | 142 | AHOLD | 17 | 127 | | 14 | 15 |
| A5 | 195 | D3 | 141 | BE0# | 31 | | | 19 | 21 |
| A6 | 193 | D4 | 140 | BE1# | 32 | | | 20 | 28 |
| A7 | 192 | D5 | 130 | BE2# | 33 | | | 22 | 36 |
| A8 | 190 | D6 | 129 | BE3# | 34 | | | 23 | 43 |
| A9 | 187 | D7 | 126 | BLAST# | 204 | | | 25 | 52 |
| A10 | 186 | D8 | 124 | BOFF# | 6 | | | 29 | 53 |
| A11 | 182 | D9 | 123 | BRDY# | 5 | | | 35 | 55 |
| A12 | 180 | D10 | 119 | BREQ | 30 | | | 38 | 57 |
| A13 | 178 | D11 | 118 | BS16# | 7 | | | 42 | 61 |
| A14 | 177 | D12 | 117 | BS8# | 8 | | | 44 | 76 |
| A15 | 174 | D13 | 116 | CACHE# | 70 | | | 45 | 81 |
| A16 | 173 | D14 | 113 | CLK | 24 | | | 54 | 88 |
| A17 | 171 | D15 | 112 | CLKMUL | 11 | | | 56 | 94 |
| A18 | 166 | D16 | 108 | D/C# | 39 | | | 60 | 97 |
| A19 | 165 | D17 | 103 | DP0 | 145 | | | 62 | 104 |
| A20 | 164 | D18 | 101 | DP1 | 125 | | | 69 | 105 |
| A21 | 161 | D19 | 100 | DP2 | 109 | | | 77 | 107 |
| A22 | 160 | D20 | 99 | DP3 | 90 | | | 80 | 110 |
| A23 | 159 | D21 | 93 | EADS# | 46 | | | 82 | 115 |
| A24 | 158 | D22 | 92 | FERR# | 66 | | | 86 | 120 |
| A25 | 154 | D23 | 91 | FLUSH# | 49 | | | 89 | 122 |
| A26 | 153 | D24 | 87 | HITM# | 63 | | | 95 | 132 |
| A27 | 152 | D25 | 85 | HLDA | 26 | | | 98 | 135 |
| A28 | 151 | D26 | 84 | HOLD | 16 | | | 102 | 138 |
| A29 | 149 | D27 | 83 | IGNNE# | 72 | | | 106 | 146 |
| A30 | 148 | D28 | 79 | INTR | 50 | | | 111 | 156 |
| A31 | 147 | D29 | 78 | INV | 71 | | | 114 | 157 |
| | | D30 | 75 | KEN# | 13 | | | 121 | 170 |
| | | D31 | 74 | LOCK# | 207 | | | 128 | 175 |
| | | | | M/IO# | 37 | | | 131 | 181 |

Table 4. Pin Cross Reference for 208-Lead SQFP Package (Sheet 2 of 2)

| Address | Pin # | Data | Pin # | Control | Pin # | NC | V _{CC5} | V _{CC} | V _{SS} |
|---------|-------|------|-------|-----------|-------|----|------------------|-----------------|-----------------|
| | | | | NMI | 51 | | | 133 | 184 |
| | | | | PCD | 41 | | | 134 | 189 |
| | | | | PCHK# | 4 | | | 136 | 199 |
| | | | | PLOCK# | 206 | | | 137 | 201 |
| | | | | PWT | 40 | | | 139 | 208 |
| | | | | RDY# | 12 | | | 150 | |
| | | | | RESERVED# | 194 | | | 155 | |
| | | | | RESET | 48 | | | 162 | |
| | | | | SMI# | 65 | | | 163 | |
| | | | | SMIACT# | 59 | | | 169 | |
| | | | | SRESET | 58 | | | 172 | |
| | | | | STPCLK# | 73 | | | 176 | |
| | | | | TCK | 18 | | | 179 | |
| | | | | TDI | 168 | | | 183 | |
| | | | | TDO | 68 | | | 185 | |
| | | | | TMS | 167 | | | 188 | |
| | | | | WB/WT# | 64 | | | 191 | |
| | | | | W/R# | 27 | | | 198 | |
| | | | | | | | | 200 | |
| | | | | | | | | 205 | |

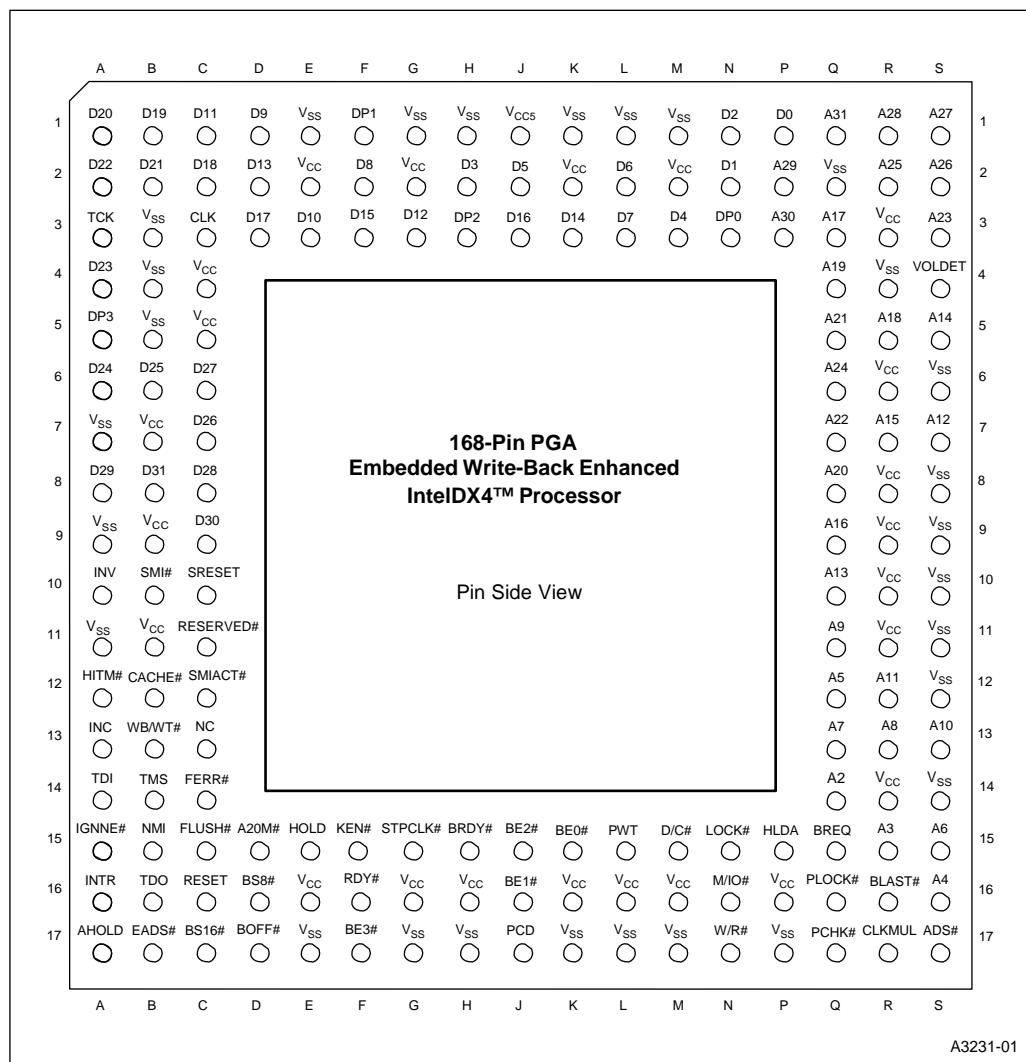


Figure 3. Package Diagram for 168-Pin PGA Embedded Write-Back Enhanced IntelDX4™ Processor

Table 5. Pinout Differences for 168-Pin PGA Package

| Pin # | Embedded IntelDX2™ Processor | Embedded Write-Back Enhanced IntelDX4™ Processor |
|-------|------------------------------|--|
| A10 | INC | INV |
| A12 | INC | HITM# |
| B12 | INC | CACHE# |
| B13 | INC | WB/WT# |
| J1 | V _{CC} | V _{CC5} |
| R17 | INC | CLKMUL |
| S4 | NC | VOLDET |

Table 6. Pin Assignment for 168-Pin PGA Package (Sheet 1 of 2)

| Pin # | Description | Pin # | Description | Pin # | Description |
|-------|-----------------|-------|------------------|-------|-----------------|
| A1 | D20 | D17 | BOFF# | P2 | A29 |
| A2 | D22 | E1 | V _{SS} | P3 | A30 |
| A3 | TCK | E2 | V _{CC} | P15 | HLDA |
| A4 | D23 | E3 | D10 | P16 | V _{CC} |
| A5 | DP3 | E15 | HOLD | P17 | V _{SS} |
| A6 | D24 | E16 | V _{CC} | Q1 | A31 |
| A7 | V _{SS} | E17 | V _{SS} | Q2 | V _{SS} |
| A8 | D29 | F1 | DP1 | Q3 | A17 |
| A9 | V _{SS} | F2 | D8 | Q4 | A19 |
| A10 | INV | F3 | D15 | Q5 | A21 |
| A11 | V _{SS} | F15 | KEN# | Q6 | A24 |
| A12 | HITM# | F16 | RDY# | Q7 | A22 |
| A13 | INC | F17 | BE3# | Q8 | A20 |
| A14 | TDI | G1 | V _{SS} | Q9 | A16 |
| A15 | IGNNE# | G2 | V _{CC} | Q10 | A13 |
| A16 | INTR | G3 | D12 | Q11 | A9 |
| A17 | AHOLD | G15 | STPCLK# | Q12 | A5 |
| B1 | D19 | G16 | V _{CC} | Q13 | A7 |
| B2 | D21 | G17 | V _{SS} | Q14 | A2 |
| B3 | V _{SS} | H1 | V _{SS} | Q15 | BREQ |
| B4 | V _{SS} | H2 | D3 | Q16 | PLOCK# |
| B5 | V _{SS} | H3 | DP2 | Q17 | PCHK# |
| B6 | D25 | H15 | BRDY# | R1 | A28 |
| B7 | V _{CC} | H16 | V _{CC} | R2 | A25 |
| B8 | D31 | H17 | V _{SS} | R3 | V _{CC} |
| B9 | V _{CC} | J1 | V _{CC5} | R4 | V _{SS} |
| B10 | SMI# | J2 | D5 | R5 | A18 |
| B11 | V _{CC} | J3 | D16 | R6 | V _{CC} |
| B12 | CACHE# | J15 | BE2# | R7 | A15 |
| B13 | WB/WT# | J16 | BE1# | R8 | V _{CC} |
| B14 | TMS | J17 | PCD | R9 | V _{CC} |
| B15 | NMI | K1 | V _{SS} | R10 | V _{CC} |
| B16 | TDO | K2 | V _{CC} | R11 | V _{CC} |
| B17 | EADS# | K3 | D14 | R12 | A11 |
| C1 | D11 | K15 | BE0# | R13 | A8 |
| C2 | D18 | K16 | V _{CC} | R14 | V _{CC} |
| C3 | CLK | K17 | V _{SS} | R15 | A3 |
| C4 | V _{CC} | L1 | V _{SS} | R16 | BLAST# |
| C5 | V _{CC} | L2 | D6 | R17 | CLKMUL |

Table 6. Pin Assignment for 168-Pin PGA Package (Sheet 2 of 2)

| Pin # | Description | Pin # | Description | Pin # | Description |
|-------|-------------|-------|-----------------|-------|-----------------|
| C6 | D27 | L3 | D7 | S1 | A27 |
| C7 | D26 | L15 | PWT | S2 | A26 |
| C8 | D28 | L16 | V _{CC} | S3 | A23 |
| C9 | D30 | L17 | V _{SS} | S4 | VOLDET |
| C10 | SRESET | M1 | V _{SS} | S5 | A14 |
| C11 | RESERVED# | M2 | V _{CC} | S6 | V _{SS} |
| C12 | SMIACT# | M3 | D4 | S7 | A12 |
| C13 | NC | M15 | D/C# | S8 | V _{SS} |
| C14 | FERR# | M16 | V _{CC} | S9 | V _{SS} |
| C15 | FLUSH# | M17 | V _{SS} | S10 | V _{SS} |
| C16 | RESET | N1 | D2 | S11 | V _{SS} |
| C17 | BS16# | N2 | D1 | S12 | V _{SS} |
| D1 | D9 | N3 | DP0 | S13 | A10 |
| D2 | D13 | N15 | LOCK# | S14 | V _{SS} |
| D3 | D17 | N16 | M/IO# | S15 | A6 |
| D15 | A20M# | N17 | W/R# | S16 | A4 |
| D16 | BS8# | P1 | D0 | S17 | ADS# |

Table 7. Pin Cross Reference for 168-Pin PGA Package (Sheet 1 of 2)

| Address | Pin # | Data | Pin # | Control | Pin # | NC | INC | Vcc5 | Vcc | Vss |
|---------|-------|------|-------|---------|-------|-----|-----|------|-----|-----|
| A2 | Q14 | D0 | P1 | A20M# | D15 | C13 | A13 | J1 | B7 | A7 |
| A3 | R15 | D1 | N2 | ADS# | S17 | | | | B9 | A9 |
| A4 | S16 | D2 | N1 | AHOLD | A17 | | | | B11 | A11 |
| A5 | Q12 | D3 | H2 | BE0# | K15 | | | | C4 | B3 |
| A6 | S15 | D4 | M3 | BE1# | J16 | | | | C5 | B4 |
| A7 | Q13 | D5 | J2 | BE2# | J15 | | | | E2 | B5 |
| A8 | R13 | D6 | L2 | BE3# | F17 | | | | E16 | E1 |
| A9 | Q11 | D7 | L3 | BLAST# | R16 | | | | G2 | E17 |
| A10 | S13 | D8 | F2 | BOFF# | D17 | | | | G16 | G1 |
| A11 | R12 | D9 | D1 | BRDY# | H15 | | | | H16 | G17 |
| A12 | S7 | D10 | E3 | BREQ | Q15 | | | | K2 | H1 |
| A13 | Q10 | D11 | C1 | BS16# | C17 | | | | K16 | H17 |
| A14 | S5 | D12 | G3 | BS8# | D16 | | | | L16 | K1 |
| A15 | R7 | D13 | D2 | CLK | C3 | | | | M2 | K17 |
| A16 | Q9 | D14 | K3 | CLKMUL | R17 | | | | M16 | L1 |
| A17 | Q3 | D15 | F3 | CACHE# | B12 | | | | P16 | L17 |
| A18 | R5 | D16 | J3 | D/C# | M15 | | | | R3 | M1 |
| A19 | Q4 | D17 | D3 | DP0 | N3 | | | | R6 | M17 |
| A20 | Q8 | D18 | C2 | DP1 | F1 | | | | R8 | P17 |
| A21 | Q5 | D19 | B1 | DP2 | H3 | | | | R9 | Q2 |
| A22 | Q7 | D20 | A1 | DP3 | A5 | | | | R10 | R4 |
| A23 | S3 | D21 | B2 | EADS# | B17 | | | | R11 | S6 |
| A24 | Q6 | D22 | A2 | FERR# | C14 | | | | R14 | S8 |
| A25 | R2 | D23 | A4 | FLUSH# | C15 | | | | | S9 |
| A26 | S2 | D24 | A6 | HITM# | A12 | | | | | S10 |
| A27 | S1 | D25 | B6 | HLDA | P15 | | | | | S11 |
| A28 | R1 | D26 | C7 | HOLD | E15 | | | | | S12 |
| A29 | P2 | D27 | C6 | IGNNE# | A15 | | | | | S14 |
| A30 | P3 | D28 | C8 | INTR | A16 | | | | | |
| A31 | Q1 | D29 | A8 | INV | A10 | | | | | |
| | | D30 | C9 | KEN# | F15 | | | | | |
| | | D31 | B8 | LOCK# | N15 | | | | | |
| | | | | M/IO# | N16 | | | | | |

Table 7. Pin Cross Reference for 168-Pin PGA Package (Sheet 2 of 2)

| Address | Pin # | Data | Pin # | Control | Pin # | NC | INC | Vcc5 | Vcc | Vss |
|---------|-------|------|-------|-----------|-------|----|-----|------|-----|-----|
| | | | | NMI | B15 | | | | | |
| | | | | PCD | J17 | | | | | |
| | | | | PCHK# | Q17 | | | | | |
| | | | | PLOCK# | Q16 | | | | | |
| | | | | PWT | L15 | | | | | |
| | | | | RDY# | F16 | | | | | |
| | | | | RESERVED# | C11 | | | | | |
| | | | | RESET | C16 | | | | | |
| | | | | SMI# | B10 | | | | | |
| | | | | SMIACT# | C12 | | | | | |
| | | | | SRESET | C10 | | | | | |
| | | | | STPCLK# | G15 | | | | | |
| | | | | TCK | A3 | | | | | |
| | | | | TDI | A14 | | | | | |
| | | | | TDO | B16 | | | | | |
| | | | | TMS | B14 | | | | | |
| | | | | VOLDET | S4 | | | | | |
| | | | | WB/WT# | B13 | | | | | |
| | | | | W/R# | N17 | | | | | |

3.2 Pin Quick Reference

The following is a brief pin description. For detailed signal descriptions refer to Appendix A, "Signal Descriptions," in the Embedded Intel486™ Processor Family Developer's Manual, order No. 273021.

Table 8. Embedded Write-Back Enhanced IntelDX4™ Processor Pin Descriptions (Sheet 1 of 8)

| Symbol | Type | Name and Function |
|--------------------|------|--|
| CLK | I | Clock provides the fundamental timing and internal operating frequency for the Embedded Write-Back Enhanced IntelDX4 processor. All external timing parameters are specified with respect to the rising edge of CLK. |
| ADDRESS BUS | | |
| A31-A4 | I/O | Address Lines A31–A2, together with the byte enable signals, BE3#–BE0#, define the physical area of memory or input/output space accessed. Address lines A31–A4 are used to drive addresses into the Embedded Write-Back Enhanced IntelDX4 processor to perform cache line invalidation. Input signals must meet setup and hold times t_{22} and t_{23} . A31–A2 are not driven during bus or address hold. |
| A3–A2 | O | |
| BE3# | O | Byte Enable signals indicate active bytes during read and write cycles. During the first cycle of a cache fill, the external system should assume that all byte enables are active. BE3#–BE0# are active LOW and are not driven during bus hold. |
| BE2# | O | BE3# applies to D31–D24 |
| BE1# | O | BE2# applies to D23–D16 |
| BE0# | O | BE1# applies to D15–D8 |
| | | BE0# applies to D7–D0 |
| DATA BUS | | |
| D31–D0 | I/O | Data Lines. D7–D0 define the least significant byte of the data bus; D31–D24 define the most significant byte of the data bus. These signals must meet setup and hold times t_{22} and t_{23} for proper operation on reads. These pins are driven during the second and subsequent clocks of write cycles. |
| DATA PARITY | | |
| DP3–DP0 | I/O | There is one Data Parity pin for each byte of the data bus. Data parity is generated on all write data cycles with the same timing as the data driven by the Embedded Write-Back Enhanced IntelDX4 processor. Even parity information must be driven back into the processor on the data parity pins with the same timing as read information to ensure that the correct parity check status is indicated by the Embedded Write-Back Enhanced IntelDX4 processor. The signals read on these pins do not affect program execution. Input signals must meet setup and hold times t_{22} and t_{23} . DP3–DP0 must be connected to V_{CC} through a pull-up resistor in systems that do not use parity. DP3–DP0 are active HIGH and are driven during the second and subsequent clocks of write cycles. |
| PCHK# | O | Parity Status is driven on the PCHK# pin the clock after ready for read operations. The parity status is for data sampled at the end of the previous clock. A parity error is indicated by PCHK# being LOW. Parity status is only checked for enabled bytes as indicated by the byte enable and bus size signals. PCHK# is valid only in the clock immediately after read data is returned to the processor. At all other times PCHK# is inactive (HIGH). PCHK# is never floated. |

Table 8. Embedded Write-Back Enhanced IntelDX4™ Processor Pin Descriptions (Sheet 2 of 8)

| Symbol | Type | Name and Function | | | |
|-----------------------------|------|--|--------------------|--------------|--|
| BUS CYCLE DEFINITION | | | | | |
| M/I/O# | O | Memory/Input-Output , Data/Control and Write/Read lines are the primary bus definition signals. These signals are driven valid as the ADS# signal is asserted. | | | |
| D/C# | O | | | | |
| W/R# | O | | | | |
| | | M/I/O# | D/C# | W/R# | Bus Cycle Initiated |
| | | 0 | 0 | 0 | Interrupt Acknowledge |
| | | 0 | 0 | 1 | HALT/Special Cycle (see details below) |
| | | 0 | 1 | 0 | I/O Read |
| | | 0 | 1 | 1 | I/O Write |
| | | 1 | 0 | 0 | Code Read |
| | | 1 | 0 | 1 | Reserved |
| | | 1 | 1 | 0 | Memory Read |
| | | 1 | 1 | 1 | Memory Write |
| | | HALT/Special Cycle | | | |
| | | Cycle Name | BE3# - BE0# | A4-A2 | |
| | | Shutdown | 1110 | 000 | |
| | | HALT | 1011 | 000 | |
| | | Stop Grant bus cycle | 1011 | 100 | |
| LOCK# | O | Bus Lock indicates that the current bus cycle is locked. The Embedded Write-Back Enhanced IntelDX4 processor does not allow a bus hold when LOCK# is asserted (address holds are allowed). LOCK# goes active in the first clock of the first locked bus cycle and goes inactive after the last clock of the last locked bus cycle. The last locked cycle ends when Ready is returned. LOCK# is active LOW and not driven during bus hold. Locked read cycles are not transformed into cache fill cycles when KEN# is returned active. | | | |
| PLOCK# | O | Pseudo-Lock indicates that the current bus transaction requires more than one bus cycle to complete. For the Embedded Write-Back Enhanced IntelDX4 processor, examples of such operations are segment table descriptor reads (64 bits) and cache line fills (128 bits). For Intel486 processors with on-chip Floating-Point Unit, floating-point long reads and writes (64 bits) also require more than one bus cycle to complete. The Embedded Write-Back Enhanced IntelDX4 processor drives PLOCK# active until the addresses for the last bus cycle of the transaction are driven, regardless of whether RDY# or BRDY# have been returned. Normally PLOCK# and BLAST# are inverse of each other. However, during the first bus cycle of a 64-bit floating-point write (for Intel486 processors with on-chip Floating-Point Unit) both PLOCK# and BLAST# are asserted. PLOCK# is a function of the BS8#, BS16# and KEN# inputs. PLOCK# should be sampled only in the clock in which Ready is returned. PLOCK# is active LOW and is not driven during bus hold. | | | |
| BUS CONTROL | | | | | |
| ADS# | O | Address Status output indicates that a valid bus cycle definition and address are available on the cycle definition lines and address bus. ADS# is driven active in the same clock in which the addresses are driven. ADS# is active LOW and not driven during bus hold. | | | |

Table 8. Embedded Write-Back Enhanced IntelDX4™ Processor Pin Descriptions (Sheet 3 of 8)

| Symbol | Type | Name and Function |
|----------------------|------|--|
| RDY# | I | Non-burst Ready input indicates that the current bus cycle is complete. RDY# indicates that the external system has presented valid data on the data pins in response to a read or that the external system has accepted data from the Embedded Write-Back Enhanced IntelDX4 processor in response to a write. RDY# is ignored when the bus is idle and at the end of the first clock of the bus cycle. RDY# is active during address hold. Data can be returned to the Embedded Write-Back Enhanced IntelDX4 processor while AHOOLD is active. RDY# is active LOW and is not provided with an internal pull-up resistor. RDY# must satisfy setup and hold times t_{16} and t_{17} for proper chip operation. |
| BURST CONTROL | | |
| BRDY# | I | Burst Ready input performs the same function during a burst cycle that RDY# performs during a non-burst cycle. BRDY# indicates that the external system has presented valid data in response to a read or that the external system has accepted data in response to a write. BRDY# is ignored when the bus is idle and at the end of the first clock in a bus cycle. BRDY# is sampled in the second and subsequent clocks of a burst cycle. Data presented on the data bus is strobed into the Embedded Write-Back Enhanced IntelDX4 processor when BRDY# is sampled active. If RDY# is returned simultaneously with BRDY#, BRDY# is ignored and the burst cycle is prematurely aborted. BRDY# is active LOW and is provided with a small pull-up resistor. BRDY# must satisfy the setup and hold times t_{16} and t_{17} . |
| BLAST# | O | Burst Last signal indicates that the next time BRDY# is returned, the burst bus cycle is complete. BLAST# is active for both burst and non-burst bus cycles. BLAST# is active LOW and is not driven during bus hold. |
| INTERRUPTS | | |
| RESET | I | Reset input forces the Embedded Write-Back Enhanced IntelDX4 processor to begin execution at a known state. The processor cannot begin executing instructions until at least 1 ms after V_{CC} , and CLK have reached their proper DC and AC specifications. The RESET pin must remain active during this time to ensure proper processor operation. However, for warm resets, RESET should remain active for at least 15 CLK periods. RESET is active HIGH. RESET is asynchronous but must meet setup and hold times t_{20} and t_{21} for recognition in any specific clock. |
| INTR | I | Maskable Interrupt indicates that an external interrupt has been generated. When the internal interrupt flag is set in EFLAGS, active interrupt processing is initiated. The Embedded Write-Back Enhanced IntelDX4 processor generates two locked interrupt acknowledge bus cycles in response to the INTR pin going active. INTR must remain active until the interrupt acknowledges have been performed to ensure processor recognition of the interrupt. INTR is active HIGH and is not provided with an internal pull-down resistor. INTR is asynchronous, but must meet setup and hold times t_{20} and t_{21} for recognition in any specific clock. |
| NMI | I | Non-Maskable Interrupt request signal indicates that an external non-maskable interrupt has been generated. NMI is rising-edge sensitive and must be held LOW for at least four CLK periods before this rising edge. NMI is not provided with an internal pull-down resistor. NMI is asynchronous, but must meet setup and hold times t_{20} and t_{21} for recognition in any specific clock. |

Table 8. Embedded Write-Back Enhanced IntelDX4™ Processor Pin Descriptions (Sheet 4 of 8)

| Symbol | Type | Name and Function |
|------------------------|------|---|
| SRESET | I | Soft Reset pin duplicates all functionality of the RESET pin except that the SMBASE register retains its previous value. For soft resets, SRESET must remain active for at least 15 CLK periods. SRESET is active HIGH. SRESET is asynchronous but must meet setup and hold times t_{20} and t_{21} for recognition in any specific clock. |
| SMI# | I | System Management Interrupt input invokes System Management Mode (SMM). SMI# is a falling-edge triggered signal which forces the Embedded Write-Back Enhanced IntelDX4 processor into SMM at the completion of the current instruction. SMI# is recognized on an instruction boundary and at each iteration for repeat string instructions. SMI# does not break LOCKed bus cycles and cannot interrupt a currently executing SMM. The Embedded Write-Back Enhanced IntelDX4 processor latches the falling edge of one pending SMI# signal while it is executing an existing SMI#. The nested SMI# is not recognized until after the execution of a Resume (RSM) instruction. |
| SMIACT# | O | System Management Interrupt Active , an active LOW output, indicates that the Embedded Write-Back Enhanced IntelDX4 processor is operating in SMM. It is asserted when the processor begins to execute the SMI# state save sequence and remains active LOW until the processor executes the last state restore cycle out of SMRAM. |
| STPCLK# | I | Stop Clock Request input signal indicates a request was made to turn off or change the CLK input frequency. When the Embedded Write-Back Enhanced IntelDX4 processor recognizes a STPCLK#, it stops execution on the next instruction boundary (unless superseded by a higher priority interrupt), empties all internal pipelines and write buffers, and generates a Stop Grant bus cycle. STPCLK# is active LOW. STPCLK# must be pulled high via a 10-KW pullup resistor. STPCLK# is an asynchronous signal, but must remain active until the Embedded Write-Back Enhanced IntelDX4 processor issues the Stop Grant bus cycle. STPCLK# may be de-asserted at any time after the processor has issued the Stop Grant bus cycle. |
| BUS ARBITRATION | | |
| BREQ | O | Bus Request signal indicates that the Embedded Write-Back Enhanced IntelDX4 processor has internally generated a bus request. BREQ is generated whether or not the processor is driving the bus. BREQ is active HIGH and is never floated. |
| HOLD | I | Bus Hold Request allows another bus master complete control of the Embedded Write-Back Enhanced IntelDX4 processor bus. In response to HOLD going active, the processor floats most of its output and input/output pins. HLDA is asserted after completing the current bus cycle, burst cycle or sequence of locked cycles. The Embedded Write-Back Enhanced IntelDX4 processor remains in this state until HOLD is de-asserted. HOLD is active HIGH and is not provided with an internal pull-down resistor. HOLD must satisfy setup and hold times t_{18} and t_{19} for proper operation. |
| HLDA | O | Hold Acknowledge goes active in response to a hold request presented on the HOLD pin. HLDA indicates that the Embedded Write-Back Enhanced IntelDX4 processor has given the bus to another local bus master. HLDA is driven active in the same clock that the processor floats its bus. HLDA is driven inactive when leaving bus hold. HLDA is active HIGH and remains driven during bus hold. |

Table 8. Embedded Write-Back Enhanced IntelDX4™ Processor Pin Descriptions (Sheet 5 of 8)

| Symbol | Type | Name and Function |
|---------------------------|--------|--|
| BOFF# | I | Backoff input forces the Embedded Write-Back Enhanced IntelDX4 processor to float its bus in the next clock. The processor floats all pins normally floated during bus hold but HLDA is not asserted in response to BOFF#. BOFF# has higher priority than RDY# or BRDY#; if both are returned in the same clock, BOFF# takes effect. The Embedded Write-Back Enhanced IntelDX4 processor remains in bus hold until BOFF# is negated. If a bus cycle is in progress when BOFF# is asserted the cycle is restarted. BOFF# is active LOW and must meet setup and hold times t_{18} and t_{19} for proper operation. |
| CACHE INVALIDATION | | |
| AHOLD | I | Address Hold request allows another bus master access to the Embedded Write-Back Enhanced IntelDX4 processor's address bus for a cache invalidation cycle. The processor stops driving its address bus in the clock following AHOLD going active. Only the address bus is floated during address hold, the remainder of the bus remains active. AHOLD is active HIGH and is provided with a small internal pull-down resistor. For proper operation, AHOLD must meet setup and hold times t_{18} and t_{19} . |
| EADS# | I | External Address - This signal indicates that a valid external address has been driven onto the Embedded Write-Back Enhanced IntelDX4 processor address pins. This address is used to perform an internal cache invalidation cycle. EADS# is active LOW and is provided with an internal pull-up resistor. EADS# must satisfy setup and hold times t_{12} and t_{13} for proper operation. |
| CACHE CONTROL | | |
| KEN# | I | Cache Enable pin is used to determine whether the current cycle is cacheable. When the Embedded Write-Back Enhanced IntelDX4 processor generates a cycle that can be cached and KEN# is active one clock before RDY# or BRDY# during the first transfer of the cycle, the cycle becomes a cache line fill cycle. Returning KEN# active one clock before RDY# during the last read in the cache line fill causes the line to be placed in the on-chip cache. KEN# is active LOW and is provided with a small internal pull-up resistor. KEN# must satisfy setup and hold times t_{14} and t_{15} for proper operation. |
| FLUSH# | I | Cache Flush input forces the Embedded Write-Back Enhanced IntelDX4 processor to flush its entire internal cache. FLUSH# is active LOW and need only be asserted for one clock. FLUSH# is asynchronous but setup and hold times t_{20} and t_{21} must be met for recognition in any specific clock. |
| PAGE CACHEABILITY | | |
| PWT PCD | O O | Page Write-Through and Page Cache Disable pins reflect the state of the page attribute bits, PWT and PCD, in the page table entry, page directory entry or control register 3 (CR3) when paging is enabled. When paging is disabled, the Embedded Write-Back Enhanced IntelDX4 processor ignores the PCD and PWT bits and assumes they are zero for the purpose of caching and driving PCD and PWT pins. PWT and PCD have the same timing as the cycle definition pins (M/IO#, D/C#, and W/R#). PWT and PCD are active HIGH and are not driven during bus hold. PCD is masked by the cache disable bit (CD) in Control Register 0. |

Table 8. Embedded Write-Back Enhanced IntelDX4™ Processor Pin Descriptions (Sheet 6 of 8)

| Symbol | Type | Name and Function |
|--------------------------------|--------|--|
| BUS SIZE CONTROL | | |
| BS16# BS8# | I I | Bus Size 16 and Bus Size 8 pins (bus sizing pins) cause the Embedded Write-Back Enhanced IntelDX4 processor to run multiple bus cycles to complete a request from devices that cannot provide or accept 32 bits of data in a single cycle. The bus sizing pins are sampled every clock. The processor uses the state of these pins in the clock before Ready to determine bus size. These signals are active LOW and are provided with internal pull-up resistors. These inputs must satisfy setup and hold times t_{14} and t_{15} for proper operation. |
| ADDRESS MASK | | |
| A20M# | I | Address Bit 20 Mask pin, when asserted, causes the Embedded Write-Back Enhanced IntelDX4 processor to mask physical address bit 20 (A20) before performing a lookup to the internal cache or driving a memory cycle on the bus. A20M# emulates the address wraparound at 1 Mbyte, which occurs on the 8086 processor. A20M# is active LOW and should be asserted only when the Embedded Write-Back Enhanced IntelDX4 processor is in real mode. This pin is asynchronous but should meet setup and hold times t_{20} and t_{21} for recognition in any specific clock. For proper operation, A20M# should be sampled HIGH at the falling edge of RESET. |
| TEST ACCESS PORT | | |
| TCK | I | Test Clock , an input to the Embedded Write-Back Enhanced IntelDX4 processor, provides the clocking function required by the JTAG Boundary scan feature. TCK is used to clock state information (via TMS) and data (via TDI) into the component on the rising edge of TCK. Data is clocked out of the component (via TDO) on the falling edge of TCK. TCK is provided with an internal pull-up resistor. |
| TDI | I | Test Data Input is the serial input used to shift JTAG instructions and data into the processor. TDI is sampled on the rising edge of TCK, during the SHIFT-IR and SHIFT-DR Test Access Port (TAP) controller states. During all other TAP controller states, TDI is a "don't care." TDI is provided with an internal pull-up resistor. |
| TDO | O | Test Data Output is the serial output used to shift JTAG instructions and data out of the component. TDO is driven on the falling edge of TCK during the SHIFT-IR and SHIFT-DR TAP controller states. At all other times TDO is driven to the high impedance state. |
| TMS | I | Test Mode Select is decoded by the JTAG TAP to select test logic operation. TMS is sampled on the rising edge of TCK. To guarantee deterministic behavior of the TAP controller, TMS is provided with an internal pull-up resistor. |
| NUMERIC ERROR REPORTING | | |
| FERR# | O | The Floating Point Error pin is driven active when a floating point error occurs. FERR# is similar to the ERROR# pin on the Intel387™ Math CoProcessor. FERR# is included for compatibility with systems using DOS type floating point error reporting. FERR# will not go active if FP errors are masked in FPU register. FERR# is active LOW, and is not floated during bus hold. |

Table 8. Embedded Write-Back Enhanced IntelDX4™ Processor Pin Descriptions (Sheet 7 of 8)

| Symbol | Type | Name and Function |
|---------------------------------|------|---|
| IGNNE# | I | When the Ignore Numeric Error pin is asserted the processor will ignore a numeric error and continue executing non-control floating point instructions, but FERR# will still be activated by the processor. When IGNNE# is de-asserted the processor will freeze on a non-control floating point instruction, if a previous floating point instruction caused an error. IGNNE# has no effect when the NE bit in control register 0 is set. IGNNE# is active LOW and is provided with a small internal pull-up resistor. IGNNE# is asynchronous but setup and hold times t_{20} and t_{21} must be met to ensure recognition on any specific clock. |
| WRITE-BACK ENHANCED MODE | | |
| CACHE# | O | The CACHE# output indicates internal cacheability on read cycles and burst write-back on write cycles. CACHE# is asserted for cacheable reads, cacheable code fetches and write-backs. It is driven inactive for non-cacheable reads, I/O cycles, special cycles, and write-through cycles. |
| FLUSH# | I | Cache FLUSH# is an existing pin that operates differently if the processor is configured as Enhanced Bus mode (write-back). FLUSH# causes the processor to write back all modified lines and flush (invalidate) the cache. FLUSH# is asynchronous, but must meet setup and hold times t_{20} and t_{21} for recognition in any specific clock. |
| HITM# | O | The Hit/Miss to a Modified Line pin is a cache coherency protocol pin that is driven only in Enhanced Bus mode. When a snoop cycle is run, HITM# indicates that the processor contains the snooped line and that the line has been modified. Assertion of HITM# implies that the line will be written back in its entirety, unless the processor is already in the process of doing a replacement write-back of the same line. |
| INV | I | The Invalidation Request pin is a cache coherency protocol pin that is used only in the Enhanced Bus mode. It is sampled by the processor on EADS#-driven snoop cycles. It is necessary to assert this pin to get the effect of the processor invalidate cycle on write-through-only lines. INV also invalidates the write-back lines. However, if the snooped line is modified, the line will be written back and then invalidated. INV must satisfy setup and hold times t_{12} and t_{13} for proper operation. |
| PLOCK# | O | In the Enhanced bus mode, Pseudo-Lock Output is always driven inactive. In this mode, a 64-bit data read (caused by an FP operand access or a segment descriptor read) is treated as a multiple cycle read request, which may be a burst or a non-burst access based on whether BRDY# or RDY# is returned by the system. Because only write-back cycles (caused by snoop write-back or replacement write-back) are write burstable, a 64-bit write will be driven out as two non-burst bus cycles. BLAST# is asserted during both writes. |
| SRESET | I | For the Embedded Write-Back Enhanced IntelDX4 processor, Soft RESET operates similar to other the Intel486 processors. On SRESET, the internal SMRAM base register retains its previous value, does not flush, write-back or disable the internal cache. Because SRESET is treated as an interrupt, it is possible to have a bus cycle while SRESET is asserted. SRESET is serviced only on an instruction boundary. SRESET is asynchronous but must meet setup and hold times t_{20} and t_{21} for recognition in any specific clock. |

Table 8. Embedded Write-Back Enhanced IntelDX4™ Processor Pin Descriptions (Sheet 8 of 8)

| Symbol | Type | Name and Function |
|---------------------------------|------|---|
| WB/WT# | I | The Write-Back/Write-Through pin enables Enhanced Bus mode (write-back cache). It also defines a cached line as write-through or write-back. For cache configuration, WB/WT# must be valid during RESET and be active for at least two clocks before and two clocks after RESET is de-asserted. To define write-back or write-through configuration of a line, WB/WT# is sampled in the same clock as the first RDY# or BRDY# is returned during a line fill (allocation) cycle. |
| CLKMUL, VCC5, AND VOLDET | | |
| CLKMUL | I | The Clock Multiplier input, defined during device RESET, defines the ratio of internal core frequency to external bus frequency. If sampled low, the core frequency operates at twice the external bus frequency (speed doubled mode). If driven high, speed triple mode is selected. CLKMUL has an internal pull-up speed to V_{cc} . A 10-K pullup resistor is recommended when the pin is tied high. |
| V_{cc5} | I | The 5V reference voltage input is the reference voltage for the 5V-tolerant I/O buffers. This signal should be connected to $+5V \pm 5\%$ for use with 5V logic. If all inputs are from 3V logic, this pin should be connected to 3.3V. |
| VOLDET | O | A Voltage Detect signal allows external system logic to distinguish between a 5V Intel486 processor and the 3.3V IntelDX4 processor. This signal is active LOW for a 3.3V IntelDX4 processor. This pin is available only on the PGA version of the Embedded Write-Back Enhanced IntelDX4 processor. |
| RESERVED PINS | | |
| RESERVED# | I | Reserved is reserved for future use. This pin MUST be connected to an external pull-up resistor circuit. The recommended resistor value is 10 kOhms. The pull-up resistor must be connected only to the RESERVED# pin. Do not share this resistor with other pins requiring pull-ups. |

Table 9. Output Pins

| Name | Active Level | Output Signal | | |
|-------------------|--------------|-----------------------------|-------------------------|---|
| | | Floated During Address Hold | Floated During Bus Hold | During Stop Grant and Stop Clock States |
| BREQ | HIGH | | | Previous State ¹ |
| HLDA | HIGH | | | As per HOLD |
| BE3#-BE0# | LOW | | • | Previous State |
| PWT, PCD | HIGH | | • | Previous State |
| W/R#, M/IO#, D/C# | HIGH/LOW | | • | Previous State |
| LOCK# | LOW | | • | HIGH (inactive) |
| PLOCK# | LOW | | • | HIGH (inactive) |
| ADS# | LOW | | • | HIGH (inactive) |
| BLAST# | LOW | | • | Previous State |
| PCHK# | LOW | | | Previous State |
| FERR# | LOW | | | Previous State |
| A3-A2 | HIGH | • | • | Previous State |
| SMIACT# | LOW | | | Previous State |
| CACHE# | LOW | • | • | HIGH ² |
| HITM# | LOW | • | • | HIGH ² |
| VOLDET | LOW | | | LOW |

NOTES:

1. The term "Previous State" means that the processor maintains the logic level applied to the signal pin just before the processor entered the Stop Grant state. This conserves power by preventing the signal pin from floating.
2. For the case of snoop cycles (via EADS#) during Stop Grant state, CACHE# and HITM# can go active depending on the snoop hit in the internal cache.

Table 10. Input/Output Pins

| Name | Active Level | Output Signal | | |
|---------|--------------|-----------------------------|-------------------------|---|
| | | Floated During Address Hold | Floated During Bus Hold | During Stop Grant and Stop Clock States |
| D31-D0 | HIGH | | • | Floated |
| DP3-DP0 | HIGH | | • | Floated |
| A31-A4 | HIGH | • | • | Previous State |

NOTE: The term "Previous State" means that the processor maintains the logic level applied to the signal pin just before the processor entered the Stop Grant state. This conserves power by preventing the signal pin from floating.

Table 11. Test Pins

| Name | Input or Output | Sampled/ Driven On |
|------|-----------------|---------------------|
| TCK | Input | N/A |
| TDI | Input | Rising Edge of TCK |
| TDO | Output | Falling Edge of TCK |
| TMS | Input | Rising Edge of TCK |

Table 12. Input Pins (Sheet 1 of 2)

| Name | Active Level | Synchronous/ Asynchronous | Internal Pull-Up/ Pull-Down |
|-------------|--------------|------------------------------|--------------------------------|
| CLK | | | |
| RESET | HIGH | Asynchronous | |
| SRESET | HIGH | Asynchronous | Pull-Down |
| HOLD | HIGH | Synchronous | |
| AHOLD | HIGH | Synchronous | Pull-Down |
| EADS# | LOW | Synchronous | Pull-Up |
| BOFF# | LOW | Synchronous | Pull-Up |
| FLUSH# | LOW | Asynchronous | Pull-Up |
| A20M# | LOW | Asynchronous | Pull-Up |
| BS16#, BS8# | LOW | Synchronous | Pull-Up |
| KEN# | LOW | Synchronous | Pull-Up |
| RDY# | LOW | Synchronous | |
| BRDY# | LOW | Synchronous | Pull-Up |
| INTR | HIGH | Asynchronous | |
| NMI | HIGH | Asynchronous | |
| IGNNE# | LOW | Asynchronous | Pull-Up |
| RESERVED# | LOW | Asynchronous | Pull-Up |
| SMI# | LOW | Asynchronous | Pull-Up |
| STPCLK# | LOW | Asynchronous | Pull-Up ¹ |
| INV | HIGH | Synchronous | Pull-Up |

NOTE:

1. Even though STPCLK# and CLKMUL have internal pull-up resistors, they cannot be left floating. An external 10-K_Ω pull-up resistor is needed if the STPCLK# pin is unused. CLKMUL must be driven to a valid logic level. If tied HIGH, an external 10-K_Ω pull-up resistor is recommended.

Table 12. Input Pins (Sheet 2 of 2)

| Name | Active Level | Synchronous/ Asynchronous | Internal Pull-Up/ Pull-Down |
|--------|--------------|------------------------------|--------------------------------|
| WB/WT# | HIGH/LOW | Synchronous | Pull-Down |
| CLKMUL | HIGH | | Pull-Up ¹ |
| TCK | HIGH | | Pull-Up |
| TDI | HIGH | | Pull-Up |
| TMS | HIGH | | Pull-Up |

NOTE:

1. Even though STPCLK# and CLKMUL have internal pull-up resistors, they cannot be left floating. An external 10-K pull-up resistor is needed if the STPCLK# pin is unused. CLKMUL must be driven to a valid logic level. If tied HIGH, an external 10-K pull-up resistor is recommended.

4.0 ARCHITECTURAL AND FUNCTIONAL OVERVIEW

The Embedded Write-Back Enhanced IntelDX4 processor architecture is essentially the same as the IntelDX4 processor. Refer to the Embedded Intel486™ Processor Family Developer's Manual (273021)

The Embedded Write-Back Enhanced IntelDX4 processor has one pin reserved for possible future use. This pin, an input signal, is called RESERVED# and must be connected to a 10-K pull-up resistor. The pull-up resistor must be connected only to the RESERVED# pin. **Do not share this resistor with other pins requiring pull-ups.**

4.1 CPUID Instruction

The Embedded Write-Back Enhanced IntelDX4 processor supports the CPUID instruction (see Table 13). Because not all Intel processors support the CPUID instruction, a simple test can determine if the instruction is supported. The test involves the

processor's ID Flag, which is bit 21 of the EFLAGS register. If software can change the value of this flag, the CPUID instruction is available. The actual state of the ID Flag bit is irrelevant and provides no significance to the hardware. This bit is cleared (reset to zero) upon device reset (RESET or SRESET) for compatibility with Intel486 processor designs that do not support the CPUID instruction.

CPUID-instruction details are provided here for the Embedded Write-Back Enhanced IntelDX4 processor. Refer to Intel Application Note AP-485 Intel Processor Identification with the CPUID Instruction (Order No. 241618) for a description that covers all aspects of the CPUID instruction and how it pertains to other Intel processors.

4.1.1 Operation of the CPUID Instruction

The CPUID instruction requires the software developer to pass an input parameter to the processor in the EAX register. The processor response is returned in registers EAX, EBX, EDX, and ECX.

Table 13. CPUID Instruction Description

| OP CODE | Instruction | Processor Core Clocks | Parameter passed in EAX (Input Value) | Description |
|---------|-------------|-----------------------|---------------------------------------|--------------------------|
| 0F A2 | CPUID | 9 | 0 | Vendor (Intel) ID String |
| | | 14 | 1 | Processor Identification |
| | | 9 | > 1 | Undefined (Do Not Use) |

Vendor ID String - When the parameter passed in EAX is 0 (zero), the register values returned upon instruction execution are shown in the following table.

| | | 31-----24 | 23-----16 | 15-----8 | 7-----0 |
|---|------------|-----------|-----------|----------|---------|
| High Value (= 1) | EAX | 0 0 0 0 | 0 0 0 0 | 0 0 0 0 | 0 0 0 1 |
| Vendor ID String (ASCII Characters) | EBX | u (75) | n (6E) | e (65) | G (47) |
| | EDX | I (49) | e (65) | n (6E) | i (69) |
| | ECX | l (6C) | e (65) | t (74) | n (6E) |

The values in EBX, EDX and ECX indicate an Intel processor. When taken in the proper order, they decode to the string "GenuineIntel."

The state of the WB/WT# input pin is sampled by the processor on the falling edge of the RESET signal. If WB/WT# is LOW, the processor is configured to operate in Write-Through/Standard Bus mode. If HIGH, it is configured to operate in Write-Back/Enhanced Bus mode. The value of the "Model" field of the processor signature register depends on the bus mode for which the processor is configured.

Processor Identification - When the parameter passed to EAX is 1 (one), the register values returned upon instruction execution are:

| | | 31-----14 | 13,12 | 11---8 | 7---4 | 3---0 |
|--|------------|--------------------------------|--------------------------|-------------------|------------------|------------------|
| Processor Signature for Write-Through/Stan- dard Bus mode | EAX | (Do Not Use) Intel Reserved | 0 0 Processor Type | 0 1 0 0 Family | 1 0 0 0 Model | XXXX Stepping |
| | | (Do Not Use) Intel Reserved | 0 0 Processor Type | 0 1 0 0 Family | 1 0 0 1 Model | XXXX Stepping |
| Processor Signature for Write- Back/Enhanced Bus mode | EBX | | | | | |
| | ECX | | | | | |
| (Intel releases information about stepping numbers as needed) | | | | | | |
| Intel Reserved (Do Not Use) | EBX | | | | | |
| | ECX | | | | | |
| Feature Flags | EDX | 31-----2 | 0-----0 | 1 | 0 | |
| | | | | VME | FPU | |

4.2 Identification After Reset

Processor Identification - Upon reset, the EDX register contains the processor signature:

| | | 31-----14 | 13,12 | 11---8 | 7---4 | 3---0 |
|---|-----|--------------------------------|-----------------------|-------------------|------------------|------------------|
| Processor Signature for Write-Through/Standard Bus mode | EDX | (Do Not Use) Intel Reserved | 0 0 Processor Type | 0 1 0 0 Family | 1 0 0 0 Model | XXXX Stepping |
| | | (Do Not Use) Intel Reserved | 0 0 Processor Type | 0 1 0 0 Family | 1 0 0 1 Model | XXXX Stepping |

(Intel releases information about stepping numbers as needed)

4.3 Boundary Scan (JTAG)

4.3.1 Device Identification

Tables 14 and 15 show the 32-bit code for the Embedded Write-Back Enhanced IntelDX4 processor. This code is loaded into the Device Identification Register.

Table 14. Boundary Scan Component Identification Code (Write-Through/Standard Bus Mode)

| Version | Part Number | | | | Mfg ID 009H = Intel | 1 |
|---------|----------------------------|-------------------------------|---|--|------------------------|---|
| | V _{CC} 1=3.3 V | Intel Architecture Type | Family 0100 = Intel486 CPU Family | Model 01000 = Embedded Write- Back Enhanced IntelDX4 processor | | |
| 31---28 | 27 | 26-----21 | 20---17 | 16-----12 | 11-----1 | 0 |
| XXXX | 1 | 000001 | 0100 | 01000 | 00000001001 | 1 |

(Intel releases information about version numbers as needed)

Boundary Scan Component Identification Code = x828 8013 (Hex)

Table 15. Boundary Scan Component Identification Code (Write-Back/Enhanced Bus Mode)

| Version | Part Number | | | | Mfg ID 009H = Intel | 1 |
|---------|----------------------------|-------------------------------|---|--|------------------------|---|
| | V _{CC} 1=3.3 V | Intel Architecture Type | Family 0100 = Intel486 CPU Family | Model 01001 = Embedded Write- Back Enhanced IntelDX4 processor | | |
| 31---28 | 27 | 26-----21 | 20----17 | 16-----12 | 11-----1 | 0 |
| XXXX | 1 | 000001 | 0100 | 01001 | 00000001001 | 1 |

(Intel releases information about version numbers as needed)

Boundary Scan Component Identification Code = x828 9013 (Hex)

4.3.2 Boundary Scan Register Bits and Bit Order

The boundary scan register contains a cell for each pin as well as cells for control of bidirectional and three-state pins. There are "Reserved" bits which correspond to no-connect (N/C) signals of the Embedded Write-Back Enhanced IntelDX4 processor. Control registers WRCTL, ABUSCTL, BUSCTL, and MISCCCTL are used to select the direction of bidirectional or three-state output signal pins. A "1" in these cells designates that the associated bus or bits are floated if the pins are three-state, or selected as input if they are bidirectional.

- WRCTL controls D31-D0 and DP3–DP0
- ABUSCTL controls A31-A2
- BUSCTL controls ADS#, BLAST#, PLOCK#, LOCK#, W/R#, BE0#, BE1#, BE2#, BE3#, M/IO#, D/C#, PWT, PCD, and CACHE#
- MISCCCTL controls PCHK#, HLDA, BREQ, and HITM#

The following is the bit order of the Embedded Write-Back Enhanced IntelDX4 processor boundary scan register:

| | | |
|-----|--|-----|
| TDO | A2, A3, A4, A5, RESERVED#, A6, A7, A8, A9, A10, A11, A12, A13, A14, A15, A16, A17, A18, A19, A20, A21, A22, A23, A24, A25, A26, A27, A28, A29, A30, A31, DP0, D0, D1, D2, D3, D4, D5, D6, D7, DP1, D8, D9, D10, D11, D12, D13, D14, D15, DP2, D16, D17, D18, D19, D20, D21, D22, D23, DP3, D24, D25, D26, D27, D28, D29, D30, D31, STPCLK#, IGNNE#, INV, CACHE#, FERR#, SMI#, WB/WT#, HITM#, SMIACT#, SRESET, NMI, INTR, FLUSH#, RESET, A20M#, EADS#, PCD, PWT, D/C#, M/IO#, BE3#, BE2#, BE1#, BE0#, BREQ, W/R#, HLDA, CLK, AHOLD, HOLD, KEN#, RDY#, CLKMUL, BS8#, BS16#, BOFF#, BRDY#, PCHK#, LOCK#, PLOCK#, BLAST#, ADS#, MISCCCTL, BUSCTL, ABUSCTL, WRCTL | TDI |
|-----|--|-----|

5.0 ELECTRICAL SPECIFICATIONS

5.1 Maximum Ratings

Table 16 is a stress rating only. Extended exposure to the Maximum Ratings may affect device reliability.

Furthermore, although the Embedded Write-Back Enhanced IntelDX4 processor contains protective circuitry to resist damage from electrostatic discharge, always take precautions to avoid high static voltages or electric fields.

Functional operating conditions are given in **Section 5.2, DC Specifications** and **Section 5.3, AC Specifications**.

Table 16. Absolute Maximum Ratings

| | |
|--|--|
| Case Temperature under Bias | -65 °C to +110 °C |
| Storage Temperature | -65 °C to +150 °C |
| DC Voltage on Any Pin with Respect to Ground | -0.5 V to $V_{CC5} + 0.5$ V |
| Supply Voltage V_{CC} with Respect to V_{SS} | -0.5 V to +4.6 V |
| Reference Voltage V_{CC5} with Respect to V_{SS} | -0.5 V to +6.5 V |
| Transient Voltage on any Input | The lesser of: $V_{CC5} + 1.6$ V or 6.5 V |
| Current Sink on V_{CC5} | 55 mA |

5.2 DC Specifications

The following tables show the operating supply voltages, DC I/O specifications, and component power consumption for the Embedded Write-Back Enhanced IntelDX4 processor.

Table 17. Operating Supply Voltages

| Product | V_{CC} |
|-----------------|-------------|
| FC80486DX4WB75 | 3.3 V 0.3 V |
| FC80486DX4WB100 | 3.3 V 0.3 V |
| A80486DX4WB100 | 3.3 V 0.3 V |

Table 18. DC Specifications

 Functional Operating Range: $V_{CC} = 3.3\text{ V} - 0.3\text{ V}$; $V_{CC5} = 5\text{ V} - 0.25\text{ V}$ (Note 1); $T_{CASE} = 0\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$

| Symbol | Parameter | Min. | Typ. | Max. | Unit | Notes |
|-----------|--|-----------------|------|------------------------------|---------------|------------------|
| V_{IL} | Input LOW Voltage | -0.3 | | +0.8 | V | |
| V_{IH} | Input HIGH Voltage | 2.0 | | $V_{CC5} + 0.3$ | V | Note 2 |
| V_{IHC} | Input HIGH Voltage of CLK | $V_{CC5} - 0.6$ | | $V_{CC5} + 0.3$ | V | |
| V_{OL} | Output LOW Voltage $I_{OL} = 4.0\text{ mA}$ (Address, Data, BEn) $I_{OL} = 5.0\text{ mA}$ (Definition, Control) $I_{OL} = 2.0\text{ mA}$ $I_{OL} = 100\text{ }\mu\text{A}$ | | | 0.45 0.45 0.40 0.20 | V | |
| V_{OH} | Output HIGH Voltage $I_{OH} = -2.0\text{ mA}$ | 2.4 | | | V | |
| I_{CC5} | V_{CC5} Leakage Current | | 15 | 300 | μA | Note 3 |
| I_{LI} | Input Leakage Current | | | 15 | A | Note 4 |
| I_{IH} | Input Leakage Current SRESET | | | 200 300 | A A | Note 5 Note 5 |
| I_{IL} | Input Leakage Current | | | 400 | A | Note 6 |
| I_{LO} | Output Leakage Current | | | 15 | A | |
| C_{IN} | Input Capacitance | | | 10 | pF | Note 7 |
| C_{OUT} | I/O or Output Capacitance | | | 14 | pF | Note 7 |
| C_{CLK} | CLK Capacitance | | | 12 | pF | Note 7 |

NOTES:

1. V_{CC5} should be connected to $3.3\text{ V} - 0.3\text{ V}$ in 3.3 V -only systems.
2. All inputs except CLK.
3. This parameter is for inputs without pull-up or pull-down resistors and $0\text{V} \leq V_{IN} \leq V_{CC}$.
4. This parameter is for $V_{CC5} - V_{CC} = 2.25\text{ V}$. Typical value is not 100% tested.
5. This parameter is for inputs with pull-down resistors and $V_{IH} = 2.4\text{V}$.
6. This parameter is for inputs with pull-up resistors and $V_{IL} = 0.4\text{V}$.
7. $F_C = 1\text{ MHz}$. Not 100% tested.

Table 19. I_{CC} ValuesFunctional Operating Range: $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$; $V_{CC5} = 5\text{ V} \pm 0.25\text{ V}$ (Note 1); $T_{CASE} = 0\text{ C}$ to $+85\text{ C}$

| Parameter | Operating Frequency | Typ. | Maximum | Notes |
|----------------------------------|---------------------|-------------------|--------------------|---------------|
| I_{CC} Active (Power Supply) | 75 MHz 100 MHz | | 1100 mA 1450 mA | Note 2 |
| I_{CC} Active (Thermal Design) | 75 MHz 100 MHz | 825 mA 1075 mA | 975 mA 1300 mA | Notes 3, 4, 5 |
| I_{CC} Stop Grant | 75 MHz 100 MHz | 20 mA 50 mA | 75 mA 100 mA | Note 6 |
| I_{CC} Stop Clock | 0 MHz | 600 μA | 2 mA | Note 7 |

NOTES:

1. V_{CC5} should be connected to $3.3\text{ V} \pm 0.3\text{ V}$ in 3.3 V -only systems.
2. This parameter is for proper power supply selection. It is measured using the worst case instruction mix at $V_{CC} = 3.6\text{ V}$.
3. The maximum current column is for thermal design power dissipation. It is measured using the worst case instruction mix at $V_{CC} = 3.3\text{ V}$.
4. The typical current column is the typical operating current in a system. This value is measured in a system using a typical device at $V_{CC} = 3.3\text{ V}$, running Microsoft Windows 3.1 at an idle condition. This typical value is dependent upon the specific system configuration.
5. Typical values are not 100% tested.
6. The I_{CC} Stop Grant specification refers to the I_{CC} value once the Embedded Write-Back Enhanced IntelDX4 processor enters the Stop Grant or Auto HALT Power Down state.
7. The I_{CC} Stop Clock specification refers to the I_{CC} value once the Embedded Write-Back Enhanced IntelDX4 processor enters the Stop Clock state. The V_{IH} and V_{IL} levels must be equal to V_{CC} and 0 V , respectively, in order to meet the I_{CC} Stop Clock specifications.

5.3 AC Specifications

The AC specifications for the Embedded Write-Back Enhanced IntelDX4 processor are given in this section.

Table 20. AC Characteristics

$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$; $V_{CC5} = 5\text{ V} \pm 0.25\text{ V}$ (Note 1)
 $T_{CASE} = 0\text{ C}$ to $+85\text{ C}$; $C_L = 50\text{pF}$, unless otherwise specified. (Sheet 1 of 2)

| Symbol | Parameter | Product | | | | | | |
|----------|--|---------|-----|-------|-----|------|--------|---------------------------|
| | | WB75 | | WB100 | | | | |
| | | Min | Max | Min | Max | Unit | Figure | Notes |
| | CLK Frequency | 8 | 25 | 8 | 33 | MHz | | Note 2 |
| t_1 | CLK Period | 40 | 125 | 30 | 125 | ns | 4 | |
| t_{1a} | CLK Period Stability | | 250 | | 250 | ps | 4 | Adjacent clocks Note 3 |
| t_2 | CLK High Time | 14 | | 11 | | ns | 4 | at 2V |
| t_3 | CLK Low Time | 14 | | 11 | | ns | 4 | at 0.8V |
| t_4 | CLK Fall Time | | 4 | | 3 | ns | 4 | 2V to 0.8V |
| t_5 | CLK Rise Time | | 4 | | 3 | ns | 4 | 0.8V to 2V |
| t_6 | A31–A2, PWT, PCD, BE3–BE0#, M/IO#, D/C#, W/R#, ADS#, LOCK#, FERR#, CACHE#, HITM#, BREQ, HLDA Valid Delay | 3 | 19 | 3 | 14 | ns | 8 | |
| t_7 | A31–A2, PWT, PCD, BE3–BE0#, M/IO#, D/C#, W/R#, ADS#, LOCK#, CACHE# Float Delay | | 28 | | 20 | ns | 9 | Note 3 |
| t_8 | PCHK# Valid Delay | 3 | 24 | 3 | 14 | ns | 7 | |
| t_{8a} | BLAST#, PLOCK#, SMIACT# Valid Delay | 3 | 24 | 3 | 14 | ns | 8 | |
| t_9 | BLAST#, PLOCK# Float Delay | | 28 | | 20 | ns | 9 | Note 3 |
| t_{10} | D31–D0, DP3–DP0 Write Data Valid Delay | 3 | 20 | 3 | 14 | ns | 8 | |
| t_{11} | D31–D0, DP3–DP0 Write Data Float Delay | | 28 | | 20 | ns | 9 | Note 3 |
| t_{12} | EADS#, INV Setup Time | 8 | | 5 | | ns | 5 | |
| t_{13} | EADS#, INV Hold Time | 3 | | 3 | | ns | 5 | |
| t_{14} | KEN#, BS16#, BS8#, WB/WT# Setup Time | 8 | | 5 | | ns | 5 | |
| t_{15} | KEN#, BS16#, BS8#, WB/WT# Hold Time | 3 | | 3 | | ns | 5 | |
| t_{16} | RDY#, BRDY# Setup Time | 8 | | 5 | | ns | 6 | |
| t_{17} | RDY#, BRDY# Hold Time | 3 | | 3 | | ns | 6 | |

Table 20. AC Characteristics $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$; $V_{CC5} = 5 \text{ V} - 0.25 \text{ V}$ (Note 1) $T_{CASE} = 0 \text{ }^{\circ}\text{C}$ to $+85 \text{ }^{\circ}\text{C}$; $C_L = 50 \text{ pF}$, unless otherwise specified. (Sheet 2 of 2)

| Symbol | Parameter | Product | | | | | | |
|-----------|---|---------|-----|-------|-----|------|--------|--------|
| | | WB75 | | WB100 | | | | |
| | | Min | Max | Min | Max | Unit | Figure | Notes |
| t_{18} | HOLD, AHOLD Setup Time | 8 | | 6 | | ns | 5 | |
| t_{18a} | BOFF# Setup Time | 8 | | 7 | | ns | 5 | |
| t_{19} | HOLD, AHOLD, BOFF# Hold Time | 3 | | 3 | | ns | 5 | |
| t_{20} | FLUSH#, A20M#, NMI, INTR, SMI#, STPCLK#, SRESET, RESET, IGNNE# Setup Time | 8 | | 5 | | ns | 5 | Note 4 |
| t_{21} | FLUSH#, A20M#, NMI, INTR, SMI#, STPCLK#, SRESET, RESET, IGNNE# Hold Time | 3 | | 3 | | ns | 5 | Note 4 |
| t_{22} | D31–D0, DP3–DP0, A31–A4 Read Setup Time | 5 | | 5 | | ns | 6 5 | |
| t_{23} | D31–D0, DP3–DP0, A31–A4 Read Hold Time | 3 | | 3 | | ns | 6 5 | |

NOTES:

1. V_{CC5} should be connected to 3.3 V – 0.3 V in 3.3 V-only systems.
2. 0-MHz operation is guaranteed when the STPCLK# and Stop Grant bus cycle protocol is used.
3. Not 100% tested, guaranteed by design characterization.
4. A reset pulse width of 15 CLK cycles is required for warm resets (RESET or SRESET). Power-up resets (cold resets) require RESET to be asserted for at least 1 ms after V_{CC} and CLK are stable.

Table 21. AC Specifications for the Test Access Port
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$; $V_{CC5} = 5\text{ V} \pm 0.25\text{ V}$ (Note 1) $T_{CASE} = 0\text{ C}$ to $+85\text{ C}$; $CL = 50\text{ pF}$

| Symbol | Parameter | Min | Max | Unit | Figure | Notes |
|----------|--|-----|-----|------|--------|--------|
| t_{24} | TCK Frequency | | 25 | MHz | | Note 2 |
| t_{25} | TCK Period | 40 | | ns | 10 | |
| t_{26} | TCK High Time | 10 | | ns | 10 | @ 2.0V |
| t_{27} | TCK Low Time | 10 | | ns | 10 | @ 0.8V |
| t_{28} | TCK Rise Time | | 4 | ns | 10 | Note 3 |
| t_{29} | TCK Fall Time | | 4 | ns | 10 | Note 3 |
| t_{30} | TDI, TMS Setup Time | 8 | | ns | 11 | Note 4 |
| t_{31} | TDI, TMS Hold Time | 7 | | ns | 11 | Note 4 |
| t_{32} | TDO Valid Delay | 3 | 25 | ns | 11 | Note 4 |
| t_{33} | TDO Float Delay | | 30 | ns | 11 | Note 4 |
| t_{34} | All Outputs (except TDO) Valid Delay | 3 | 25 | ns | 11 | Note 4 |
| t_{35} | All Outputs (except TDO) Float Delay | | 36 | ns | 11 | Note 4 |
| t_{36} | All Inputs (except TDI, TMS, TCK) Setup Time | 8 | | ns | 11 | Note 4 |
| t_{37} | All Inputs (except TDI, TMS, TCK) Hold Time | 7 | | ns | 11 | Note 4 |

NOTES:

1. V_{CC5} should be connected to $3.3\text{ V} \pm 0.3\text{ V}$ in 3.3 V -only systems. All inputs and outputs are TTL level.
2. TCK period = CLK period.
3. Rise/Fall times are measured between 0.8V and 2.0V . Rise/Fall times can be relaxed by 1 ns per 10-ns increase in TCK period.
4. Parameters $t_{30} - t_{37}$ are measured from TCK.

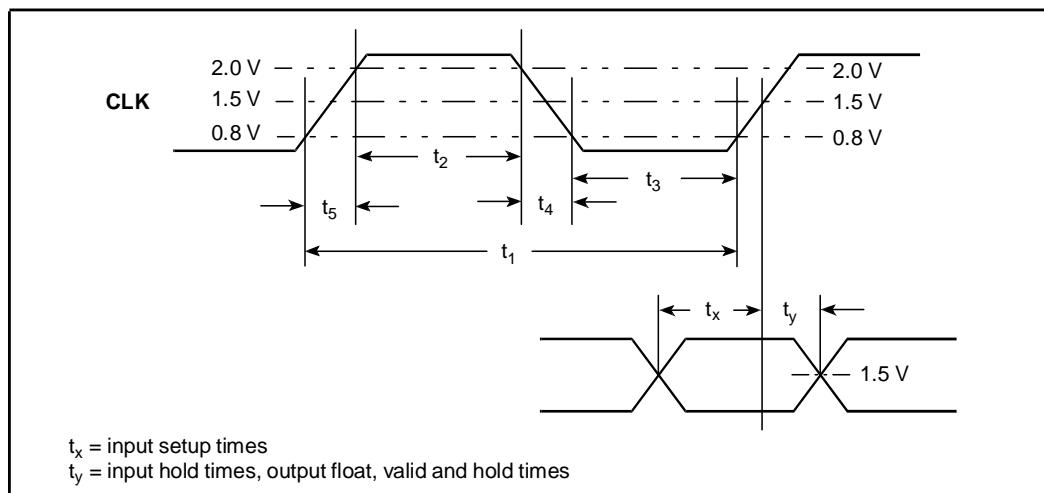


Figure 4. CLK Waveform

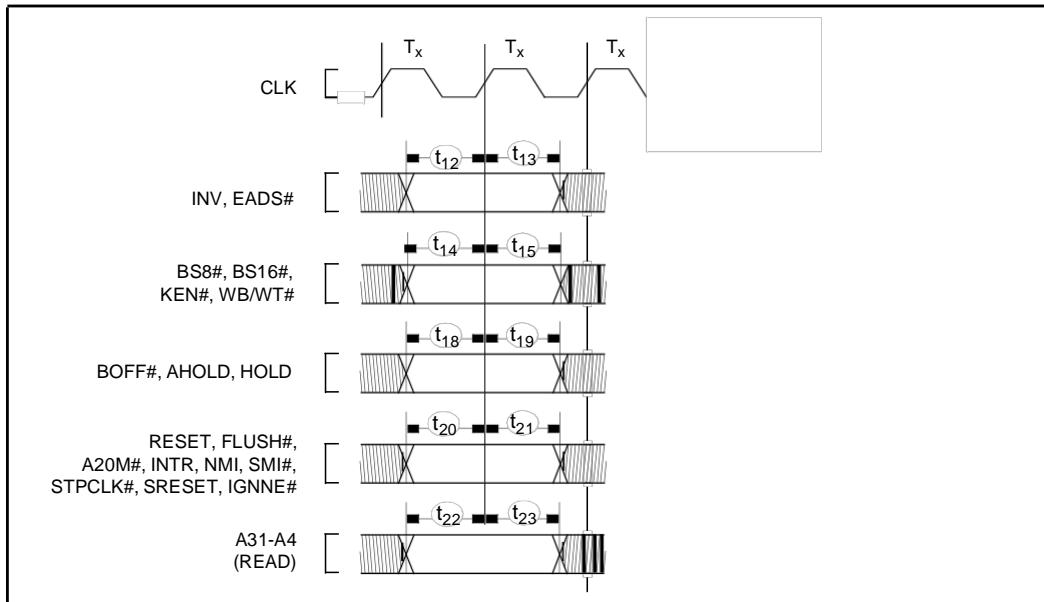


Figure 5. Input Setup and Hold Timing

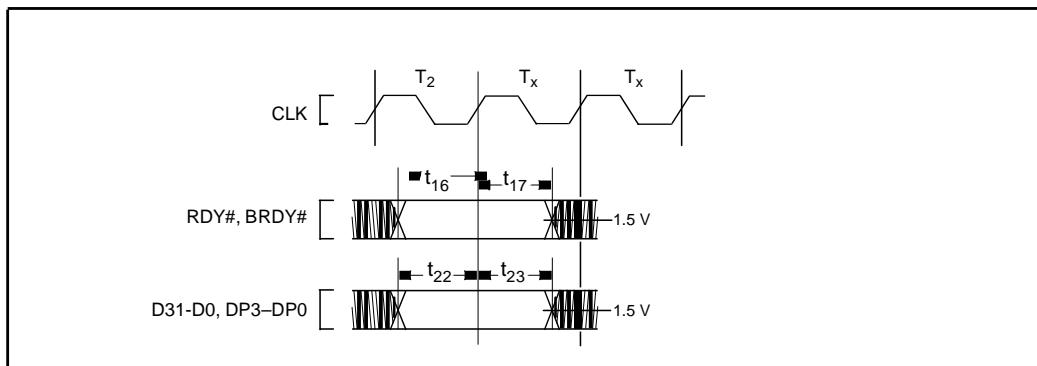


Figure 6. Input Setup and Hold Timing

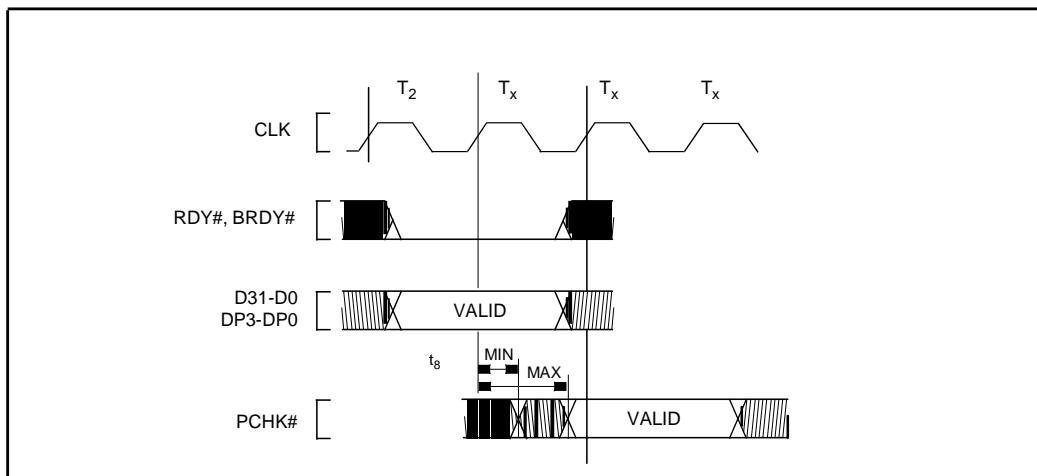


Figure 7. PCHK# Valid Delay Timing

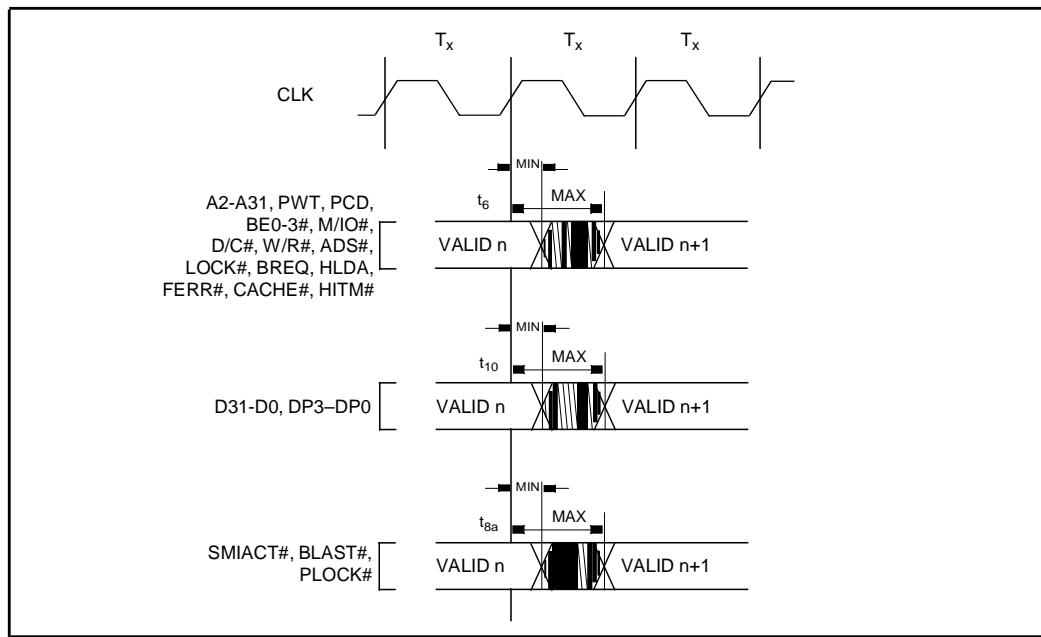


Figure 8. Output Valid Delay Timing

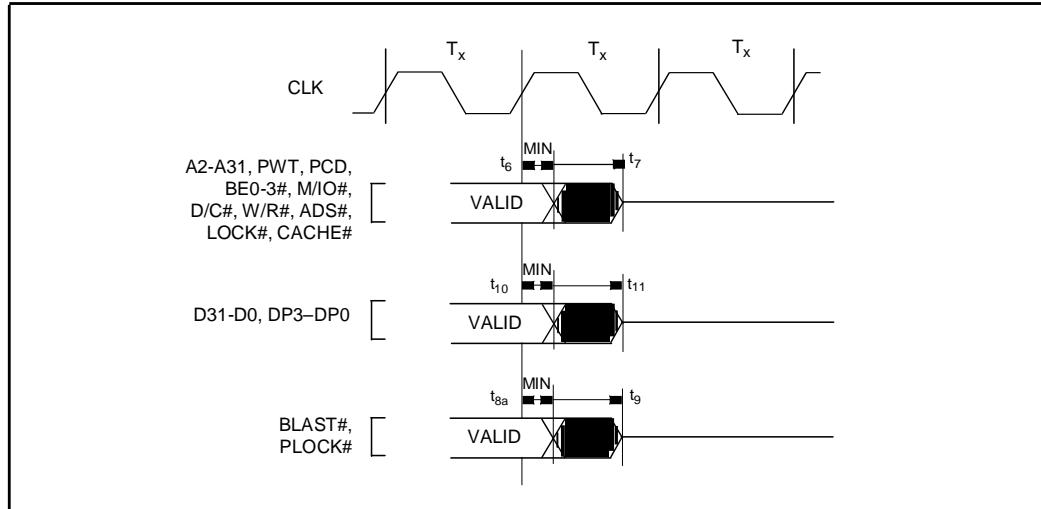


Figure 9. Maximum Float Delay Timing

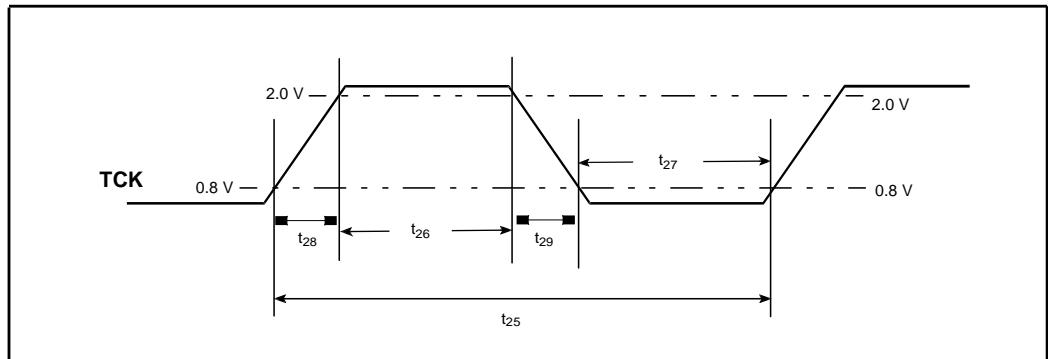


Figure 10. TCK Waveform

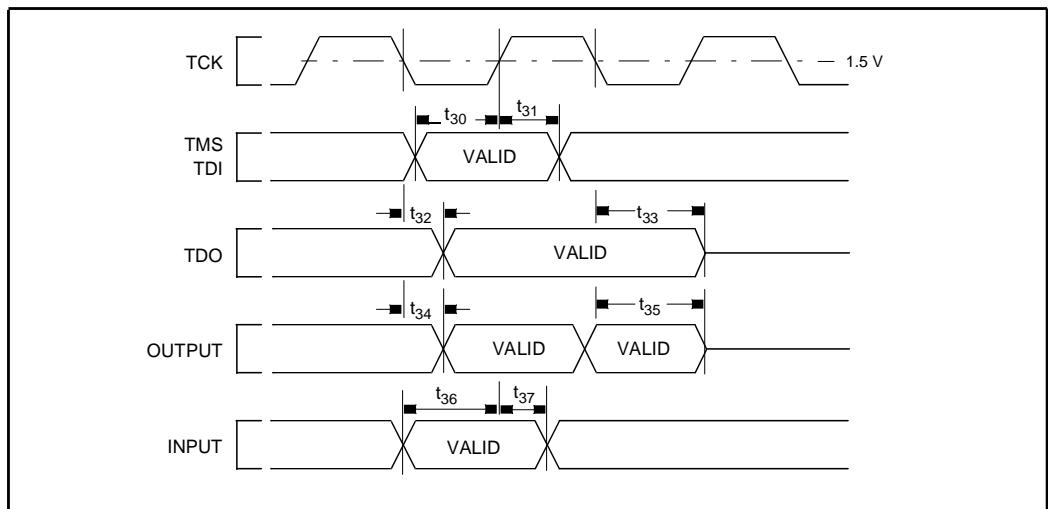
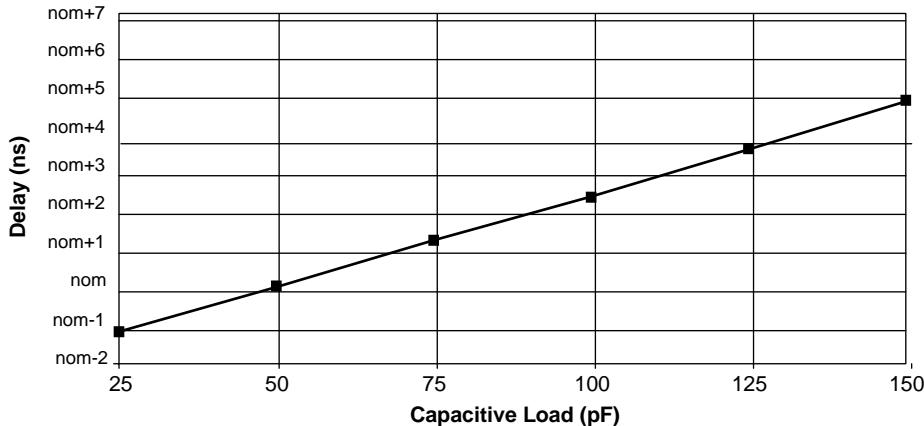


Figure 11. Test Signal Timing Diagram

5.4 Capacitive Derating Curves

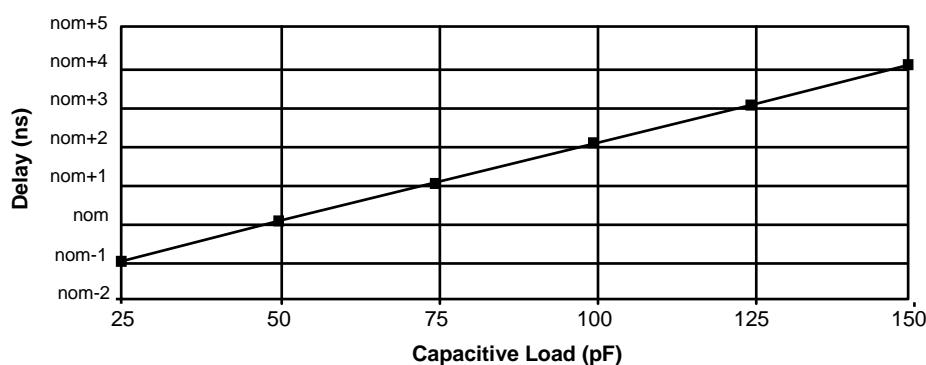
These graphs are the capacitive derating curves for the Embedded Write-Back Enhanced IntelDX4 processor.



Note: This graph will not be linear outside of the capacitive range shown.
 nom = nominal value from the AC Characteristics table.

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Figure 12. Typical Loading Delay versus Load Capacitance under Worst-Case Conditions for a Low-to-High Transition



Note: This graph will not be linear outside of the capacitive range shown.
 nom = nominal value from the AC Characteristics table.

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Figure 13. Typical Loading Delay versus Load Capacitance under Worst-Case Conditions for a High-to-Low Transition

In a mixed voltage system (processors at 3 volts, peripherals at 5 volts), the bus is driven to 5 volts by the peripheral logic. Therefore, the processor must discharge the capacitance on the bus from 5 volts to 0 volts, which takes more time than the 3 volts to 0 volts transition. Inaccurate capacitive derating impacts timing margins and may result in system failures under certain load conditions.

When designing for higher loads in mixed voltage systems, timing margins should be evaluated based on the derating curves shown in Figure 14. For more accurate delay prediction, use I/O buffer models.

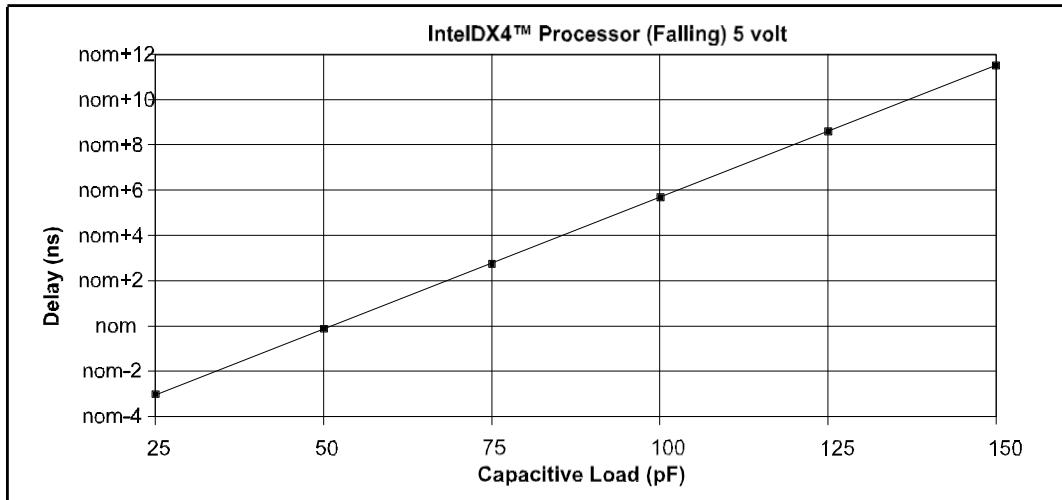


Figure 14. Typical Loading Delay versus Load Capacitance in Mixed Voltage System

6.0 MECHANICAL DATA

This section describes the packaging dimensions and thermal specifications for the Embedded Write-Back Enhanced IntelDX4 processor.

6.1 Package Dimensions

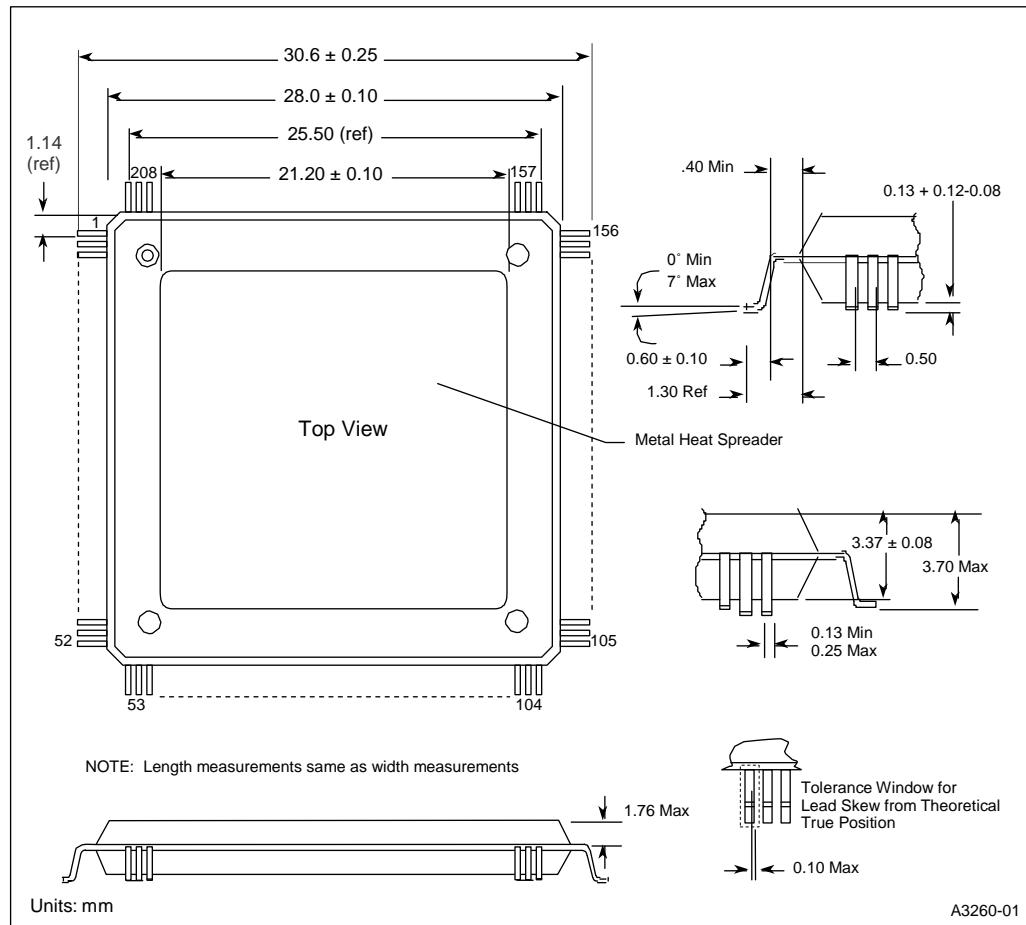


Figure 15. 208-Lead SQFP Package Dimensions

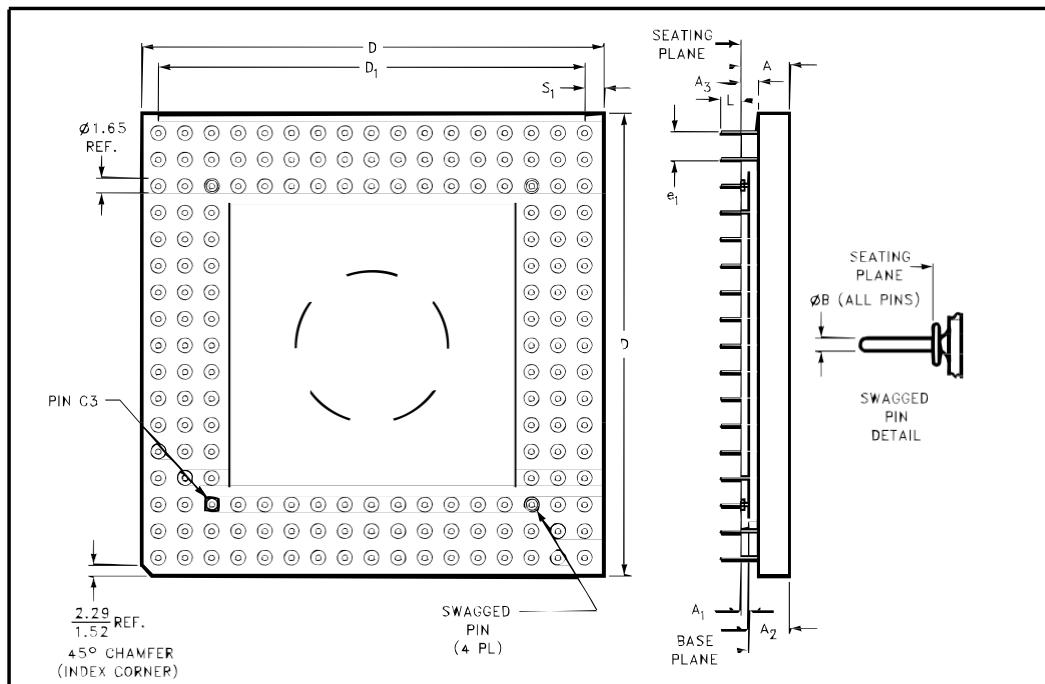


Figure 16. Principal Dimensions and Data for 168-Pin Grid Array Package

Table 22. 168-Pin Ceramic PGA Package Dimensions

| Symbol | Millimeters | | | Inches | | |
|----------------|-------------|-------|-----------|--------|-------|-----------|
| | Min | Max | Notes | Min | Max | Notes |
| A | 3.56 | 4.57 | | 0.140 | 0.180 | |
| A ₁ | 0.64 | 1.14 | SOLID LID | 0.025 | 0.045 | SOLID LID |
| A ₂ | 2.8 | 3.5 | SOLID LID | 0.110 | 0.140 | SOLID LID |
| A ₃ | 1.14 | 1.40 | | 0.045 | 0.055 | |
| B | 0.43 | 0.51 | | 0.017 | 0.020 | |
| D | 44.07 | 44.83 | | 1.735 | 1.765 | |
| D ₁ | 40.51 | 40.77 | | 1.595 | 1.605 | |
| e ₁ | 2.29 | 2.79 | | 0.090 | 0.110 | |
| L | 2.54 | 3.30 | | 0.100 | 0.130 | |
| N | 168 | | | 168 | | |
| S ₁ | 1.52 | 2.54 | | 0.060 | 0.100 | |

Table 23. Ceramic PGA Package Dimension Symbols

| Letter or Symbol | Description of Dimensions |
|------------------|---|
| A | Distance from seating plane to highest point of body |
| A ₁ | Distance between seating plane and base plane (lid) |
| A ₂ | Distance from base plane to highest point of body |
| A ₃ | Distance from seating plane to bottom of body |
| B | Diameter of terminal lead pin |
| D | Largest overall package dimension of length |
| D ₁ | A body length dimension, outer lead center to outer lead center |
| e ₁ | Linear spacing between true lead position centerlines |
| L | Distance from seating plane to end of lead |
| S ₁ | Other body dimension, outer lead center to edge of body |

NOTES:

1. Controlling dimension: millimeter.
2. Dimension "e₁" ("e") is non-cumulative.
3. Seating plane (standoff) is defined by P.C. board hole size: 0.0415–0.0430 inch.
4. Dimensions "B", "B₁", and "C" are nominal.
5. Details of Pin 1 identifier are optional.

6.2 Package Thermal Specifications

The Embedded Write-Back Enhanced IntelDX4 processor is specified for operation when the case temperature (T_C) is within the range of 0°C to 85°C. T_C may be measured in any environment to determine whether the processor is within the specified operating range.

The ambient temperature (T_A) can be calculated from T_C and T_J from the following equations:

$$\begin{aligned}
 T_J &= T_C + P * J_C \\
 T_A &= T_J - P * J_A \\
 T_C &= T_A + P * [J_A - J_C] \\
 T_A &= T_C - P * [J_A - J_C]
 \end{aligned}$$

Where T_J, T_A, T_C equals Junction, Ambient and Case Temperature respectively. J_C, J_A equals Junction-to-Case and Junction-to-Ambient thermal Resistance, respectively. P is defined as Maximum Power Consumption.

Values for J_A and J_C are given in the following tables for each product at its maximum operating frequencies. Maximum T_A is shown for each product operating at its maximum processor frequency (three times the CLK frequency). Refer to the Embedded Intel486™ Processor Family Developer's Manual (273021) for a description of the methods used to measure these characteristics.

Table 24. Thermal Resistance, J_A (C/W)

| Package | Heat Sink | J_A vs. Airflow — ft/min. (m/sec) | | | | | |
|---------------|-----------|-------------------------------------|------------|------------|------------|------------|-------------|
| | | 0 (0) | 200 (1.01) | 400 (2.03) | 600 (3.04) | 800 (4.06) | 1000 (5.07) |
| 168-Pin PGA | No | 17.5 | 15.0 | 13.0 | 11.5 | 10.0 | 9.5 |
| 168-Pin PGA | Yes | 13.5 | 8.5 | 6.5 | 5.5 | 4.5 | 4.25 |
| 208-Lead SQFP | No | 12.5 | 10.0 | 9.0 | 8.5 | | |
| 208-Lead SQFP | Yes | 10.5 | 6.5 | 5.0 | 4.0 | | |

Table 25. Thermal Resistance, J_C (C/W)

| Package | Heat Sink | J_C |
|---------------|-----------|-------|
| 168-Pin PGA | No | 2.0 |
| 168-Pin PGA | Yes | 2.0 |
| 208-Lead SQFP | No | 1.2 |
| 208-Lead SQFP | Yes | 0.8 |

Table 26. Maximum $T_{ambient}$, T_A max (C)

| Package | Heat Sink | Freq. (MHz) | Airflow — ft/min. (m/sec) | | | |
|---------------|-----------|-------------|---------------------------|------------|------------|------------|
| | | | 0 (0) | 200 (1.01) | 400 (2.03) | 600 (3.04) |
| 168-Pin PGA | No | 100 | 18.5 | 29.0 | 37.5 | 44.0 |
| 168-Pin PGA | Yes | 100 | 35.5 | 57.0 | 65.5 | 70.0 |
| 208-Lead SQFP | No | 100 | 36.5 | 46.0 | 50.0 | 52.5 |
| 208-Lead SQFP | Yes | 100 | 43.5 | 60.5 | 67.0 | 71.0 |
| 208-Lead SQFP | No | 75 | | | | |
| 208-Lead SQFP | Yes | 75 | | | | |

